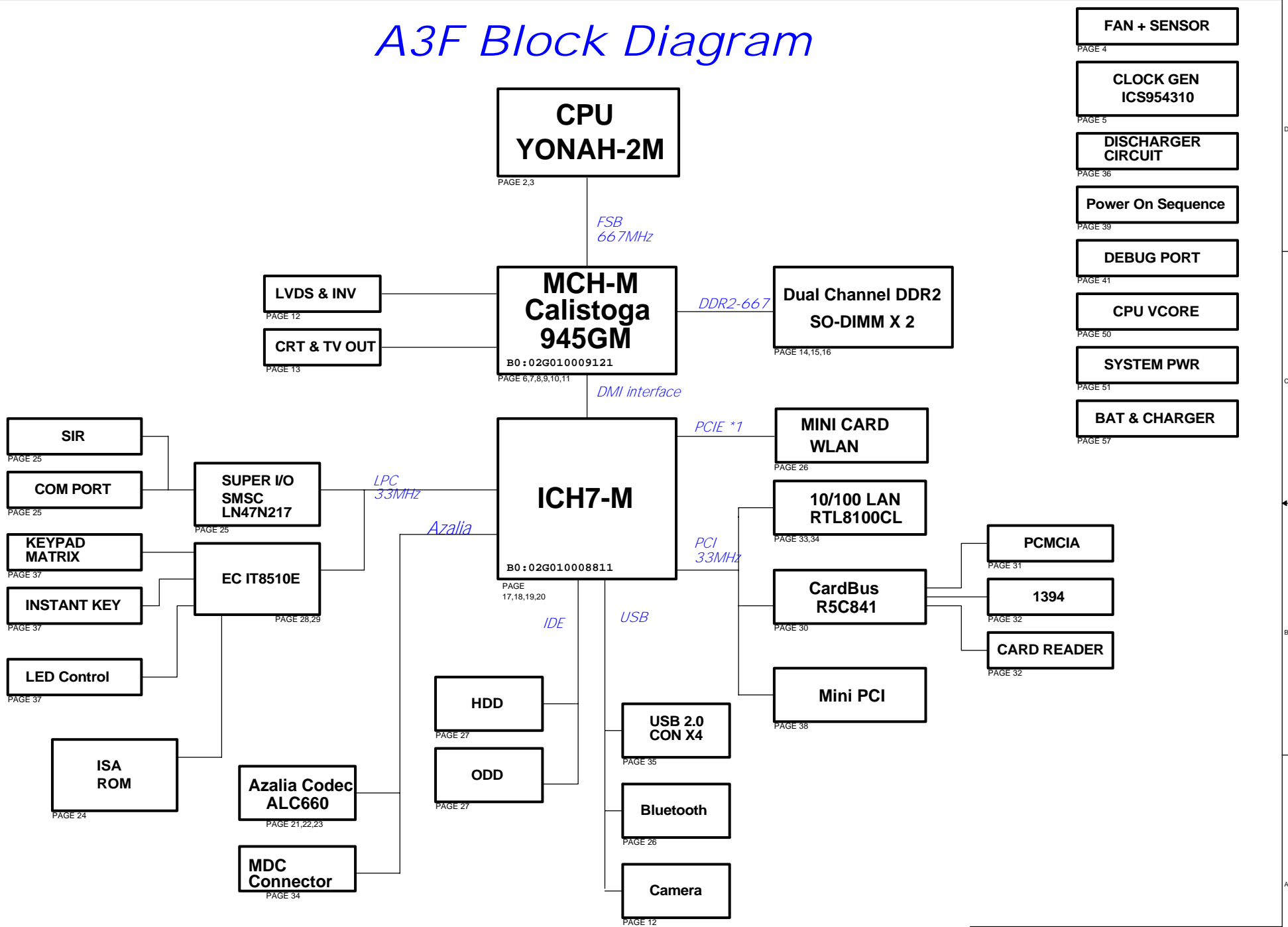
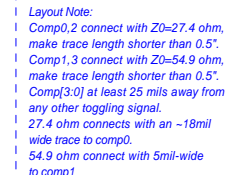
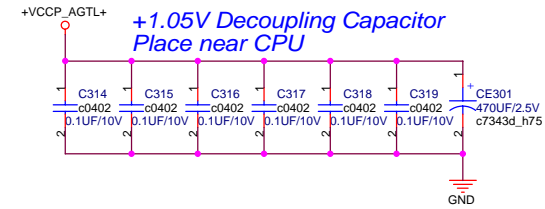
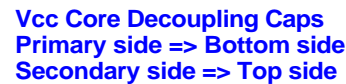
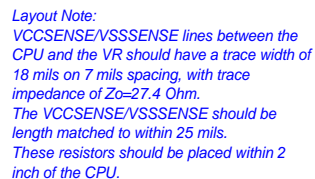


A3F Block Diagram





YUNAH FSB667			
	Min	Typ	Max
VCCP	0.997V	1.05V	1.102V
	Min	Typ	Max
ICCP			2.5A

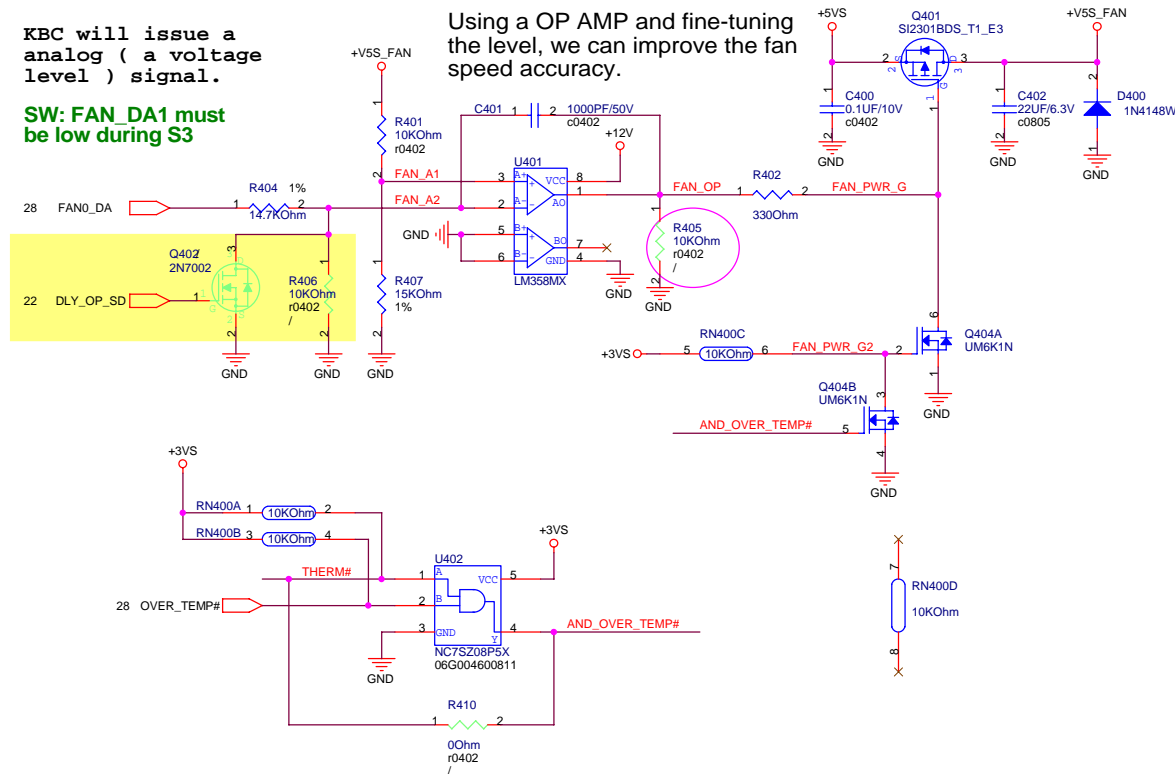


Fan Speed Control

KBC will issue a analog (a voltage level) signal.

SW: FAN_DA1 must be low during S3

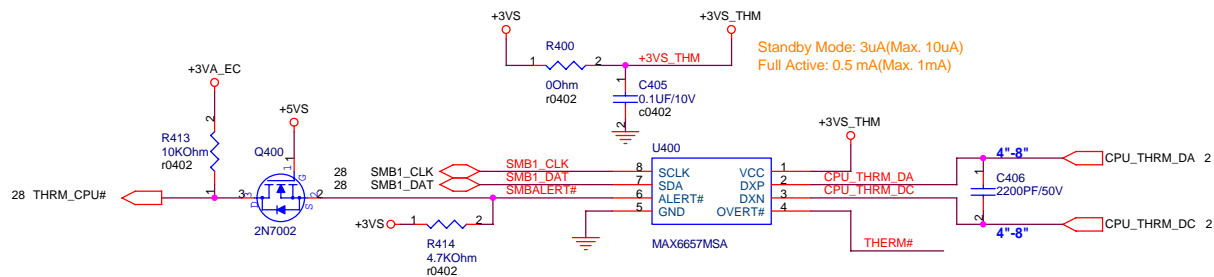
Using a OP AMP and fine-tuning the level, we can improve the fan speed accuracy.



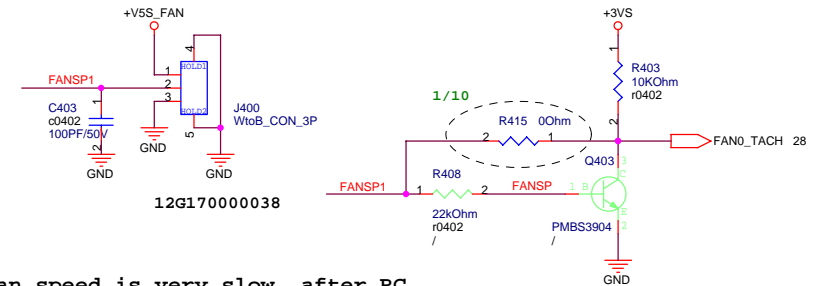
Route H_THERMDA and H_THERMDC on the same layer

-----OTHER SIGNALS
12 mils
=====GND
10 mils
=====H_THERMDA(10 mils)
10 mils
=====H_THERMDC(10 mils)
10 mils
=====GND
12 mils
-----OTHER SIGNALS

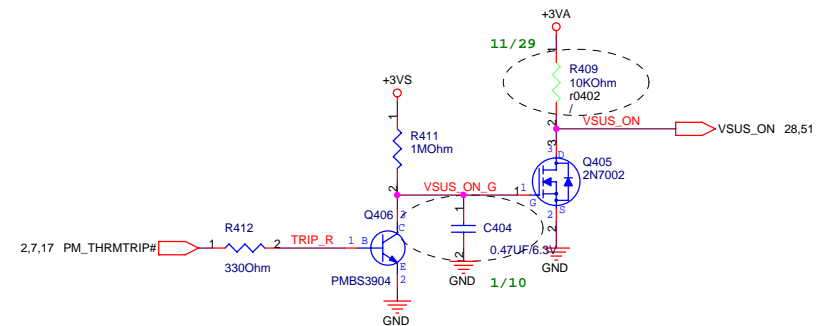
Avoid BPSB,Power

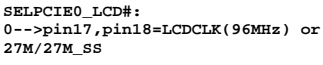
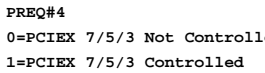
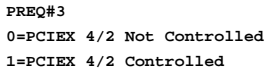
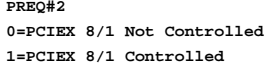
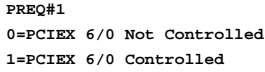
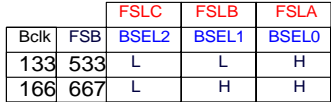


CPU FAN



When fan speed is very slow, after RC integrator the level of FANSP1 will be very low that may make south bridge do the wrong detection.



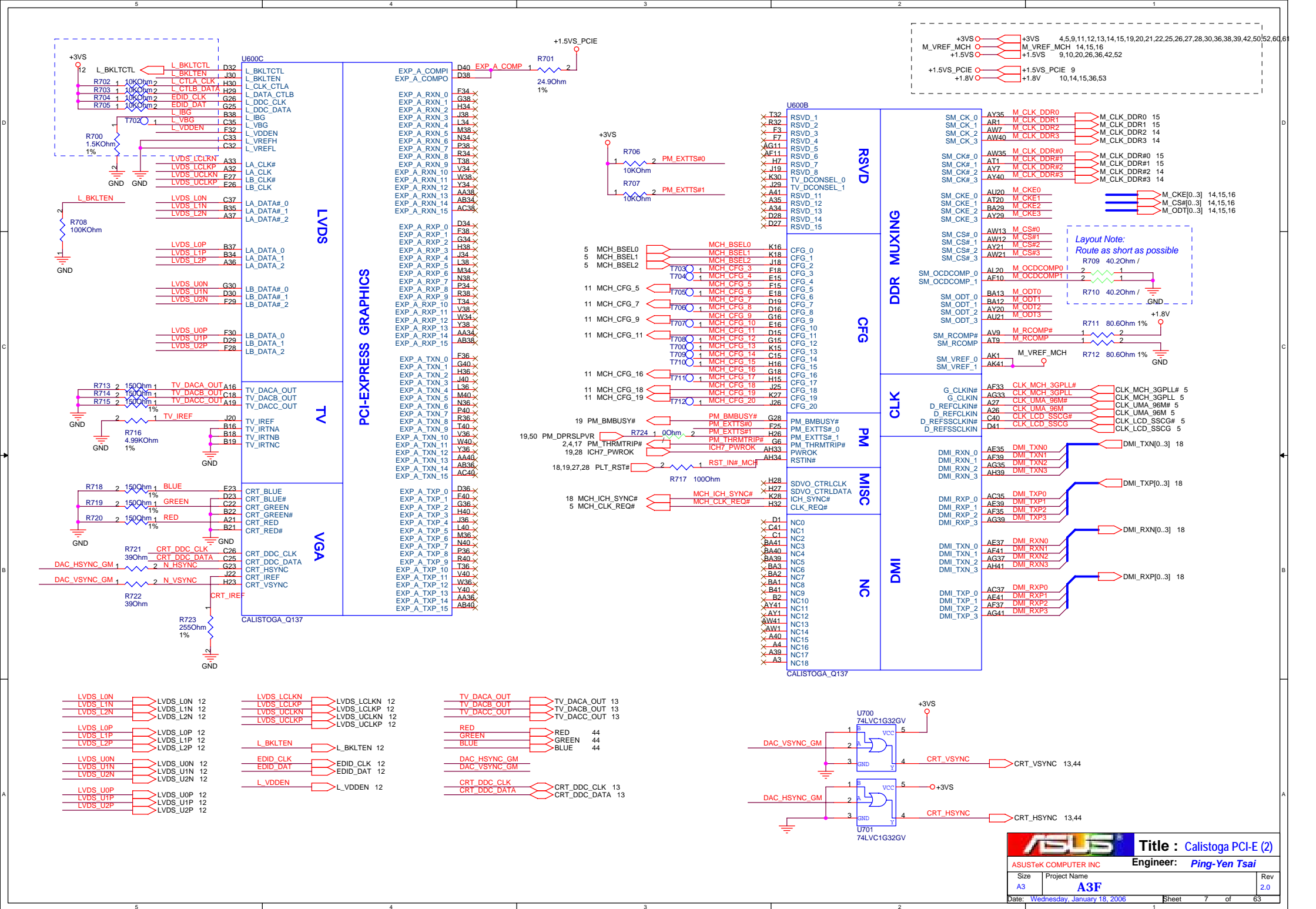


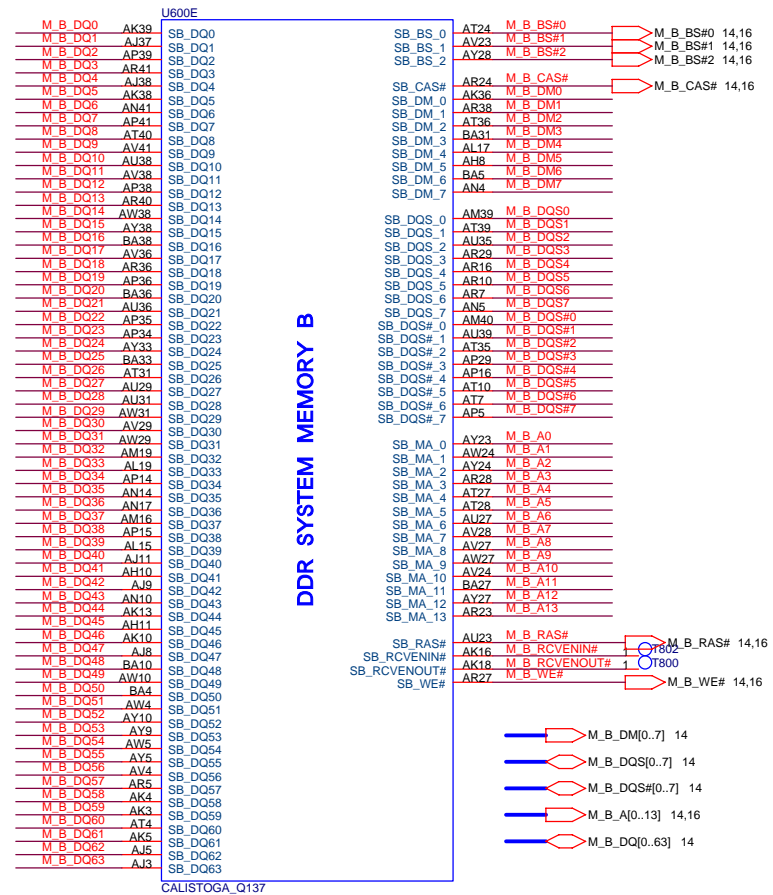
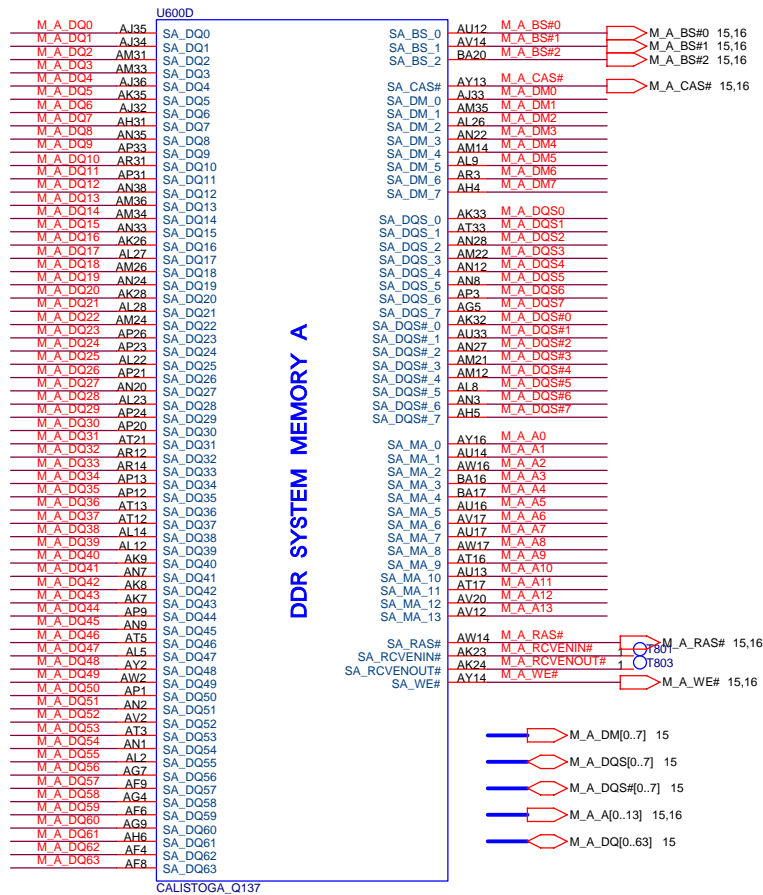
```
SELCD_27#/PCICLK_F1:
1-->pin17,pin18=LCDCLK(96MHz)
```

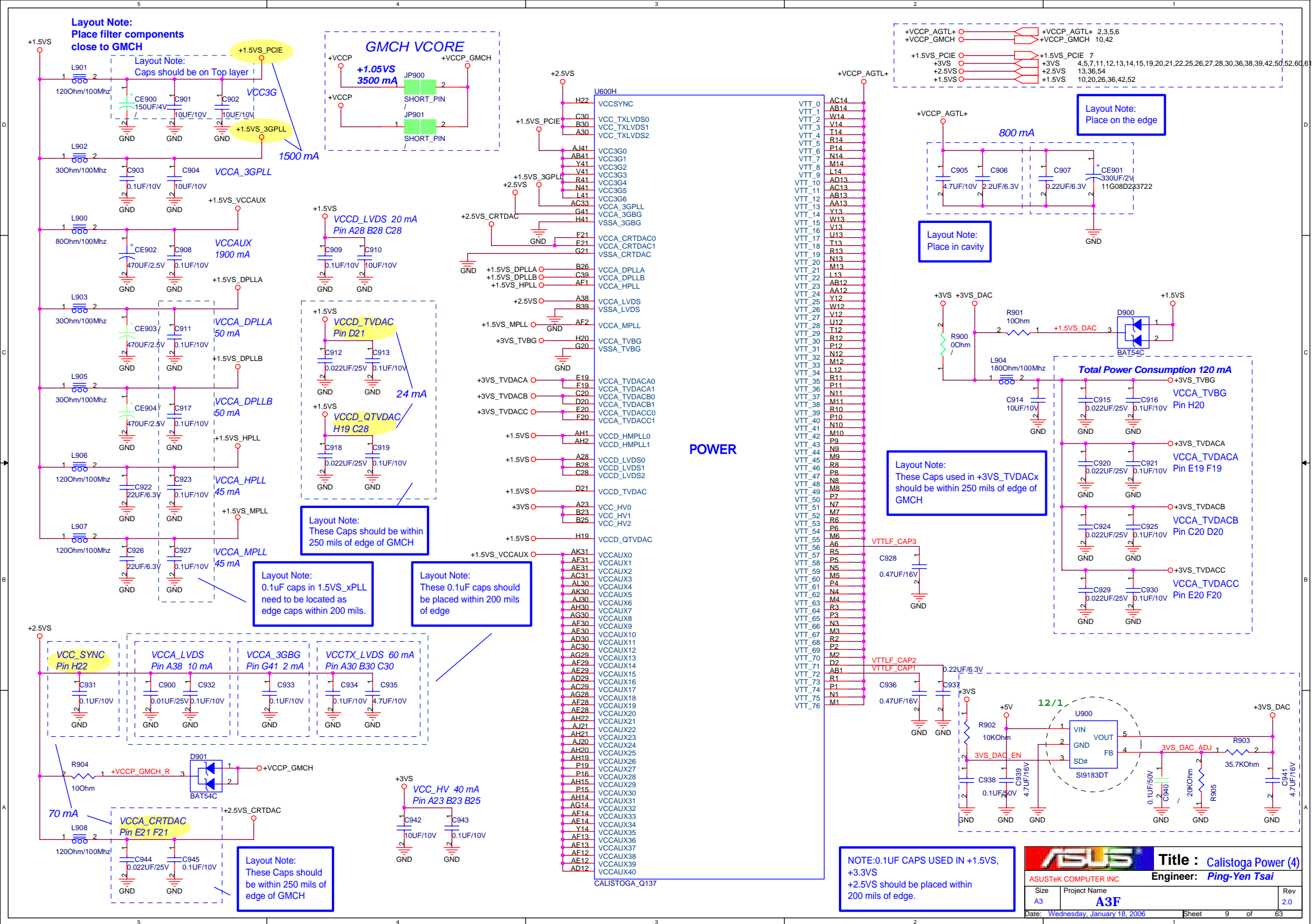
```
PCICLK2/REQ_SEL:
1-->pin40,pin41=PREQ1#,PREQ2#
```

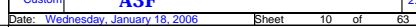
```
ITP_EN/PCICLK_F0:
1-->CPU_ITP pair
```

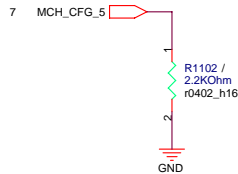
Internal Pull-Down Resistor



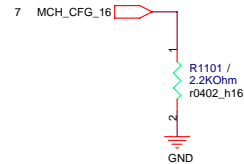




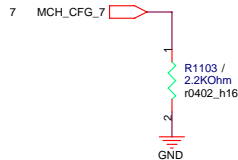




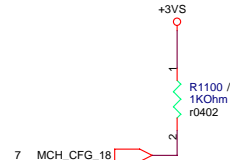
CFG5 : DMI X2 Select
 LOW = DMI X 2
HIGH = DMI X 4 (Default)



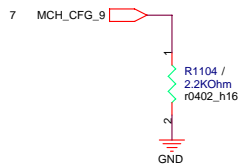
CFG16 : FSB DYNAMIC ODT
 LOW = Dynamic ODT Disabled
HIGH = Dynamic ODT Enabled (Default)



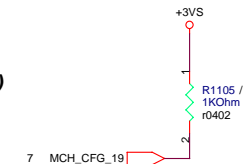
CFG7 : CPU STRAP
 LOW = Reserved
HIGH = Mobility CPU (Default)



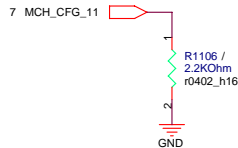
CFG18 : GMCH Core Voltage Level
 LOW = 1.05V
HIGH = 1.5V (default)



CFG9 : PCIE GRAPHIC LANE
 LOW = REVERSE LANES
HIGH = NORMAL OPERATION (Default)



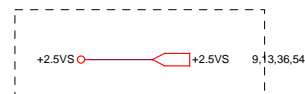
CFG19 : DMI LANE REVERSAL
LOW = NORMAL
 HIGH = LANES REVERSED



CFG11 : Reserved but need to be pull low

CFG[17..3] have internal pullup resistors.
 CFG[19..18] have internal pulldown resistors.
 SDVOCRTL_DATA has internal pulldown resistors.

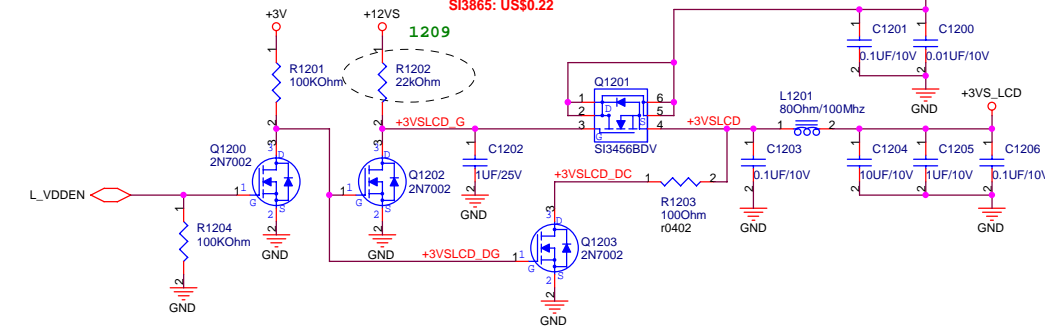
CFG All are sampled with respect to the leading edge of the GMCH PWROK		
2:0	FSB Freq select	001 = FSB533 011 = FSB667
4:3		
5	DMI X 2 Select	0 = DMI X 2 1 = DMI X 4 (Default)
6		
7	CPU Strap	0 = Reserved 1 = Mobile CPU (Default)
8		
9	PCIE Graphics Lane Reversal	0 = Reverse Lanes 1 = Normal (Default)
11:10		
13:12	XOR/ALLZ	00 = Partial Clock Gating Disable 01 = XOR Mode Enabled 10 = All-Z Mode Enabled 11 = Normal operation (Default)
15:14		
16	FSB Dynamic ODT	0 = Dynamic ODT Disabled 1 = Dynamic ODT Enabled (Default)
17		
SDVO_C TRLDATA	SDVO Present	0 = No SDVO Card Present (Default) 1 = SDVO Card Present
18	VCC select	0 = 1.05V (Default) 1 = 1.5V
19	DMI Lane Reversal	0 = Normal (Default) 1 = Reverse Lanes
20	SDVO/PCIE concurrent	0 = Only SDVO or PCIE x1 is operational(Default) 1 = SDVO and PCIE x1 are operating simultaneously via the PEG port



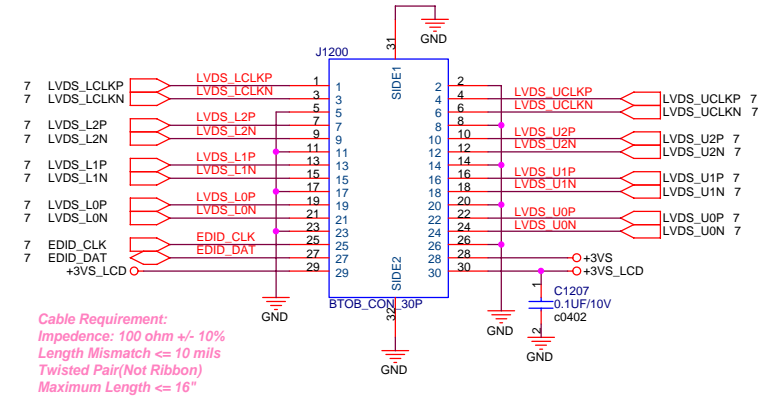
LCD Panel Power

3~3.6V
Full Active: 410 mA(Max. 500 mA)
3~3.6V
S0-S1 M: 410 mA(Max. 500 mA)

SI3865: US\$0.22



LCD LVDS Interface

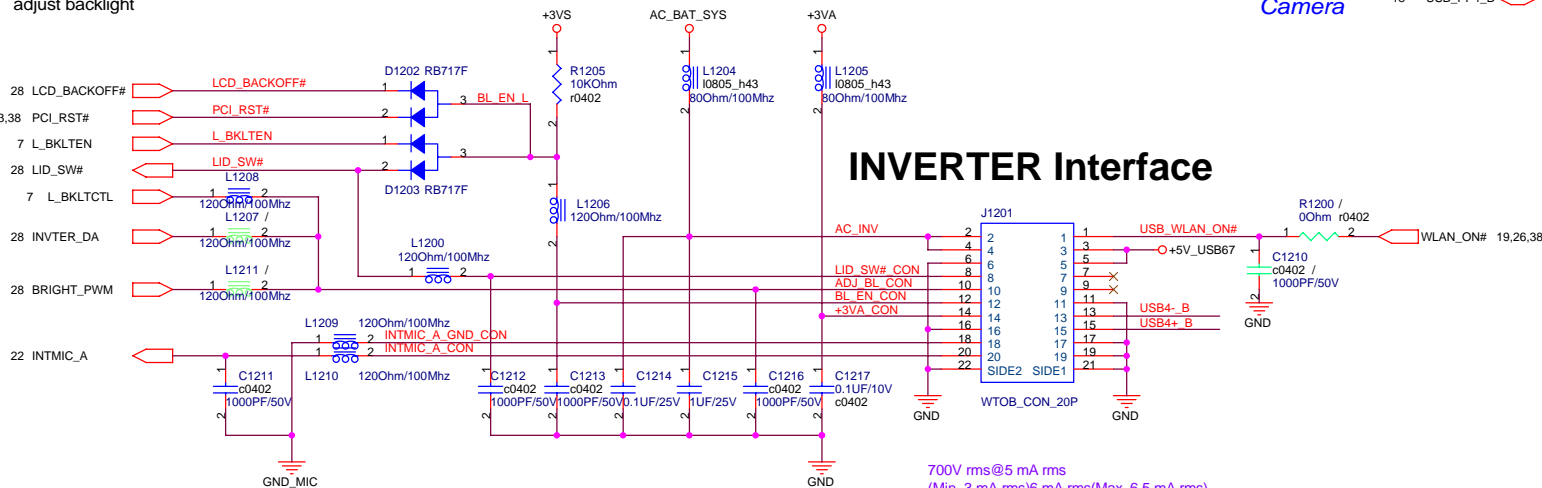


LCD Backlight Control

BIOS
LCD_BACKOFF#
When user push "Fn+F7" button
BIOS active this pin to turn On/Off backlight

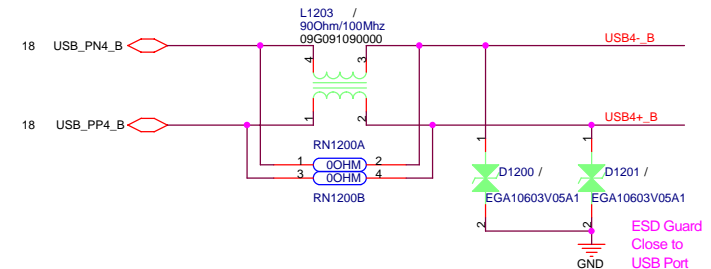
EC
INVTER_DA:
EC output D/A signal (adjust voltage level) to
adjust backlight

*Inverter Board
built in 14.1W
LCD Panel*



700V rms@5 mA rms
(Min. 3 mA rms)6 mA rms(Max. 6.5 mA rms)

USB4
For
CMOS
Camera

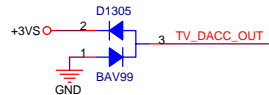
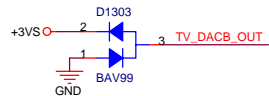
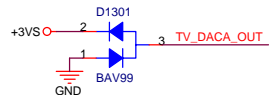
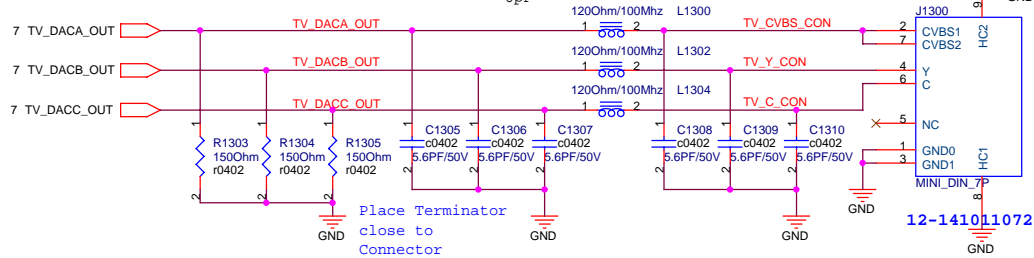


INVERTER Interface

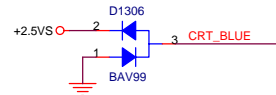
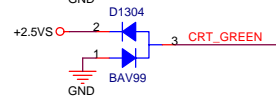
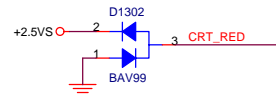
TV OUT

12G14101107D

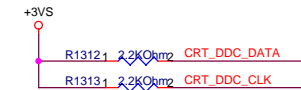
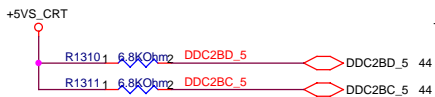
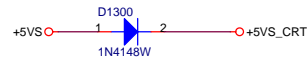
checklist suggests
150ohm/100MHz &
6pF



PLACE ESD Diodes
near TV port

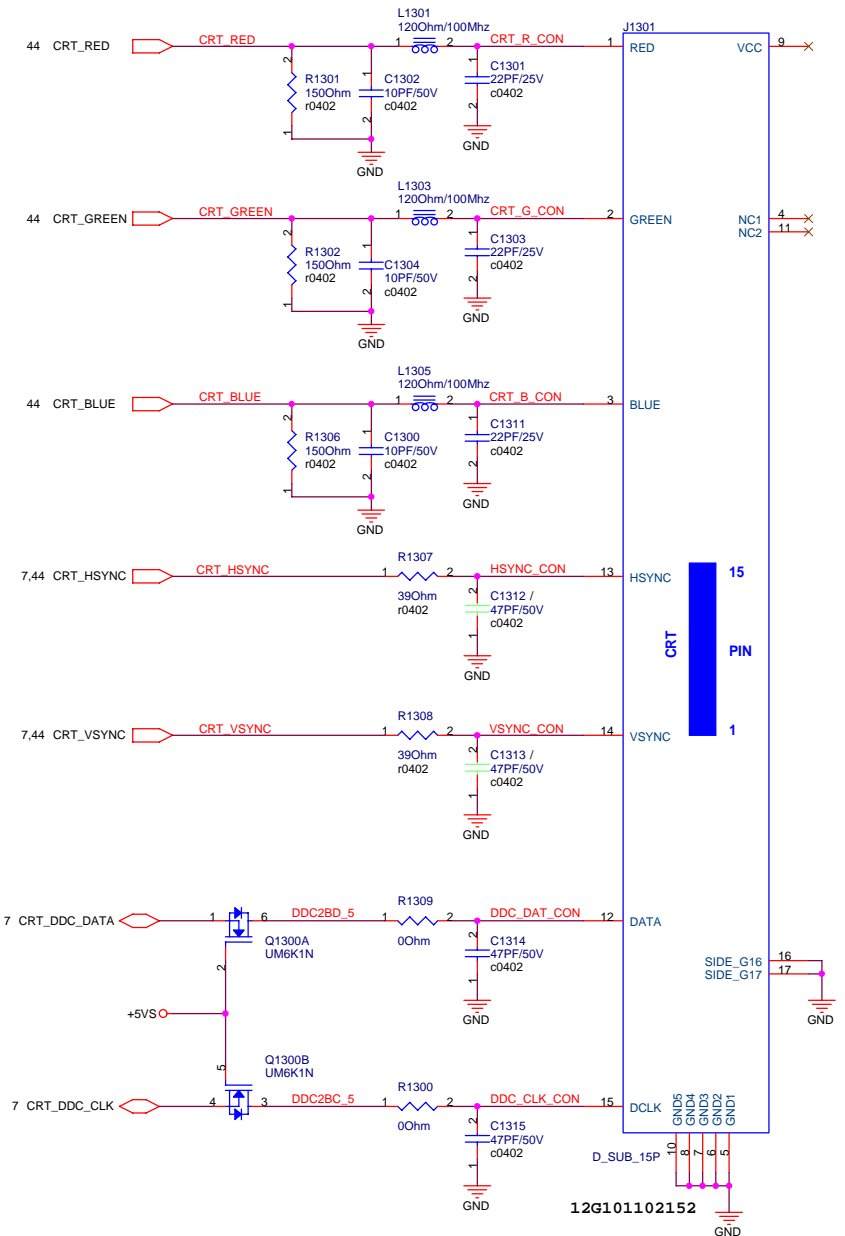


PLACE ESD Diodes
near VGA port



CRT OUT

checklist suggests 47ohm/100MHz



8 M_B_DQ[0..63]

8,16 M_B_A[0..13]

M_B A0 102
M_B A1 101
M_B A2 100
M_B A3 99
M_B A4 98
M_B A5 97
M_B A6 94
M_B A7 92
M_B A8 93
M_B A9 91
M_B A10 105
M_B A11 90
M_B A12 89
M_B A13 116

U1400A

DQ0 5
DQ1 7
DQ2 17
DQ3 19
DQ4 4
DQ5 6
DQ6 14
DQ7 16
DQ8 23
DQ9 25
DQ10 35
DQ11 37
DQ12 20
DQ13 22
DQ14 36
DQ15 38
DQ16 43
DQ17 45
DQ18 55
DQ19 57
DQ20 44
DQ21 46
DQ22 56
DQ23 58
DQ24 61
DQ25 63
DQ26 73
DQ27 75
DQ28 62
DQ29 64
DQ30 74
DQ31 76

M_B DQ1 5
M_B DQ5 7
M_B DQ2 17
M_B DQ3 19
M_B DQ4 4
M_B DQ6 14
M_B DQ7 16
M_B DQ8 23
M_B DQ12 25
M_B DQ9 35
M_B DQ11 37
M_B DQ13 20
M_B DQ10 22
M_B DQ14 36
M_B DQ15 38
M_B DQ20 43
M_B DQ17 45
M_B DQ23 55
M_B DQ22 57
M_B DQ21 44
M_B DQ16 46
M_B DQ19 56
M_B DQ18 58
M_B DQ29 61
M_B DQ28 63
M_B DQ30 73
M_B DQ24 75
M_B DQ25 62
M_B DQ26 64
M_B DQ31 74
M_B DQ32 76

A10/AP
A11
A12
A13
A14
A15
A16_BA2

M_B_BS#2

8,16 M_B_BS#2

M_B_BS#0 107
M_B_BS#1 106
M_CS#2 110
M_CS#3 115
M_CLK_DDR3 30
M_CLK_DDR#3 32
M_CLK_DDR2 164
M_CLK_DDR#2 166
M_CKE2 79
M_CKE3 80
M_B_CAS# 80
M_B_CAS# 113
M_B_RAS# 108
M_B_WE# 109

SMB_CLK_S 197
SMB_DAT_S 195

7,16 M_ODT2
7,16 M_ODT3

M_B_DM0 10
M_B_DM1 26
M_B_DM2 52
M_B_DM3 67
M_B_DM4 130
M_B_DM5 147
M_B_DM6 170
M_B_DM7 185

M_B_DQS0 13
M_B_DQS1 31
M_B_DQS2 51
M_B_DQS3 70
M_B_DQS4 131
M_B_DQS5 148
M_B_DQS6 169
M_B_DQS7 188
M_B_DQS#0 11
M_B_DQS#1 29
M_B_DQS#2 49
M_B_DQS#3 68
M_B_DQS#4 129
M_B_DQS#5 146
M_B_DQS#6 167
M_B_DQS#7 186

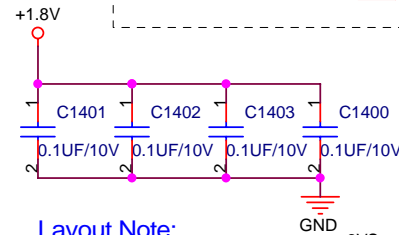
DDR_DIMM_200P_A
12G025122007

8 M_B_DM[0..7]

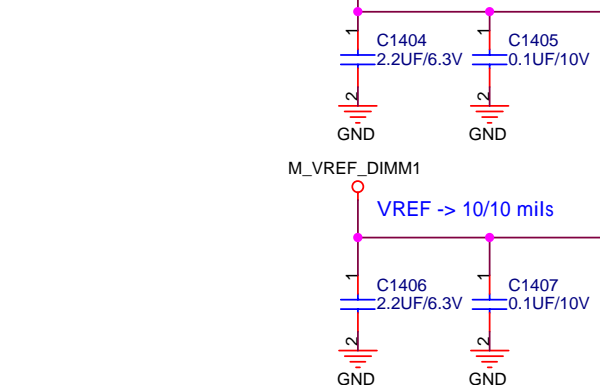
8 M_B_DQS[0..7]

8 M_B_DQS#[0..7]

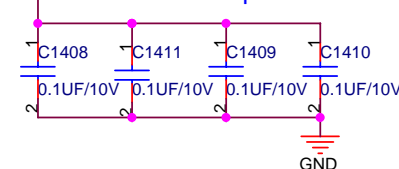
M_VREF_DIMM1 7,15,16
+1.8V 7,10,15,36,53
+3VS 4,5,7,9,11,12,13,15,19,20,21,22,25,26,27,28,30,36,38,39,42,50,52,60,61



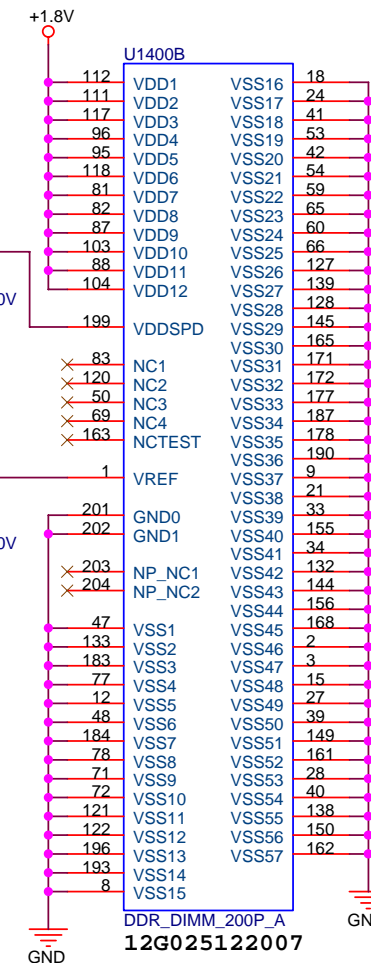
Layout Note:
Place these resistors
near the GMCH



Layout Note:
Place these Caps near SO DIMM 1



Layout Note:
Place these Caps near SO DIMM 1



Title : DDR2_SO-DIMM(1)

ASUSTeK COMPUTER INC

Engineer: Ping-Yen Tsai

Size
A4

Project Name
A3F

Rev
2.0

Date: Wednesday, January 18, 2006

Sheet 14 of 63

8 M_A_DQ[0..63]

8,16 M_A_A[0..13]

Green Part Number:12G025122006
Green Part Number:12-025122006

J1500A

M_A_A0	102	A0	DQ0	5	M_A_DQ5
M_A_A1	101	A1	DQ1	7	M_A_DQ4
M_A_A2	100	A2	DQ2	17	M_A_DQ2
M_A_A3	99	A3	DQ3	19	M_A_DQ3
M_A_A4	98	A4	DQ4	4	M_A_DQ1
M_A_A5	97	A4	DQ4	6	M_A_DQ0
M_A_A6	94	A5	DQ5	14	M_A_DQ6
M_A_A7	92	A6	DQ6	14	M_A_DQ7
M_A_A8	93	A7	DQ7	16	M_A_DQ13
M_A_A9	91	A8	DQ8	23	M_A_DQ8
M_A_A10	105	A9	DQ9	25	M_A_DQ8
M_A_A11	90	A10/AP	DQ10	35	M_A_DQ10
M_A_A12	89	A11	DQ11	37	M_A_DQ11
M_A_A13	116	A12	DQ12	20	M_A_DQ12
		A13	DQ13	22	M_A_DQ14
		A14	DQ14	36	M_A_DQ15
		A15	DQ15	38	M_A_DQ9
		A16_BA2	DQ16	43	M_A_DQ16
			DQ17	45	M_A_DQ21
			DQ18	55	M_A_DQ23
			DQ19	57	M_A_DQ19
			DQ20	44	M_A_DQ20
			DQ21	46	M_A_DQ17
			DQ22	56	M_A_DQ22
			DQ23	58	M_A_DQ18
			DQ24	61	M_A_DQ24
			DQ25	63	M_A_DQ25
			DQ26	73	M_A_DQ26
			DQ27	75	M_A_DQ27
			DQ28	62	M_A_DQ28
			DQ29	64	M_A_DQ29
			DQ30	74	M_A_DQ30
			DQ31	76	M_A_DQ31
			DQ32	123	M_A_DQ36
			DQ33	125	M_A_DQ37
			DQ34	135	M_A_DQ35
			DQ35	137	M_A_DQ34
			DQ36	124	M_A_DQ32
			DQ37	126	M_A_DQ33
			DQ38	134	M_A_DQ39
			DQ39	136	M_A_DQ38
			DQ40	141	M_A_DQ45
			DQ41	143	M_A_DQ41
			DQ42	151	M_A_DQ47
			DQ43	153	M_A_DQ46
			DQ44	140	M_A_DQ44
			DQ45	142	M_A_DQ40
			DQ46	152	M_A_DQ43
			DQ47	154	M_A_DQ42
			DQ48	157	M_A_DQ48
			DQ49	159	M_A_DQ49
			DQ50	173	M_A_DQ50
			DQ51	175	M_A_DQ51
			DQ52	158	M_A_DQ53
			DQ53	160	M_A_DQ52
			DQ54	174	M_A_DQ54
			DQ55	176	M_A_DQ55
			DQ56	179	M_A_DQ60
			DQ57	181	M_A_DQ56
			DQ58	189	M_A_DQ63
			DQ59	191	M_A_DQ59
			DQ60	180	M_A_DQ61
			DQ61	182	M_A_DQ57
			DQ62	192	M_A_DQ58
			DQ63	194	M_A_DQ62

DDR2_DIMM_200P_REV

For Data Swap

8 M_A_DM[0..7]

8 M_A_DQS[0..7]

8 M_A_DQS#[0..7]

GMCH=====>SODIMM1=>SODIMM0

+1.8V
+3VS
M_VREF_DIMM0

+1.8V
+3VS
M_VREF_DIMM0

7,10,14,36,53
4,5,7,9,11,12,13,14,19,20,21,22,25,26,27,28,30,36,38,39,42,50,52,60,61
7,14,16

Group0

Group1

Group2

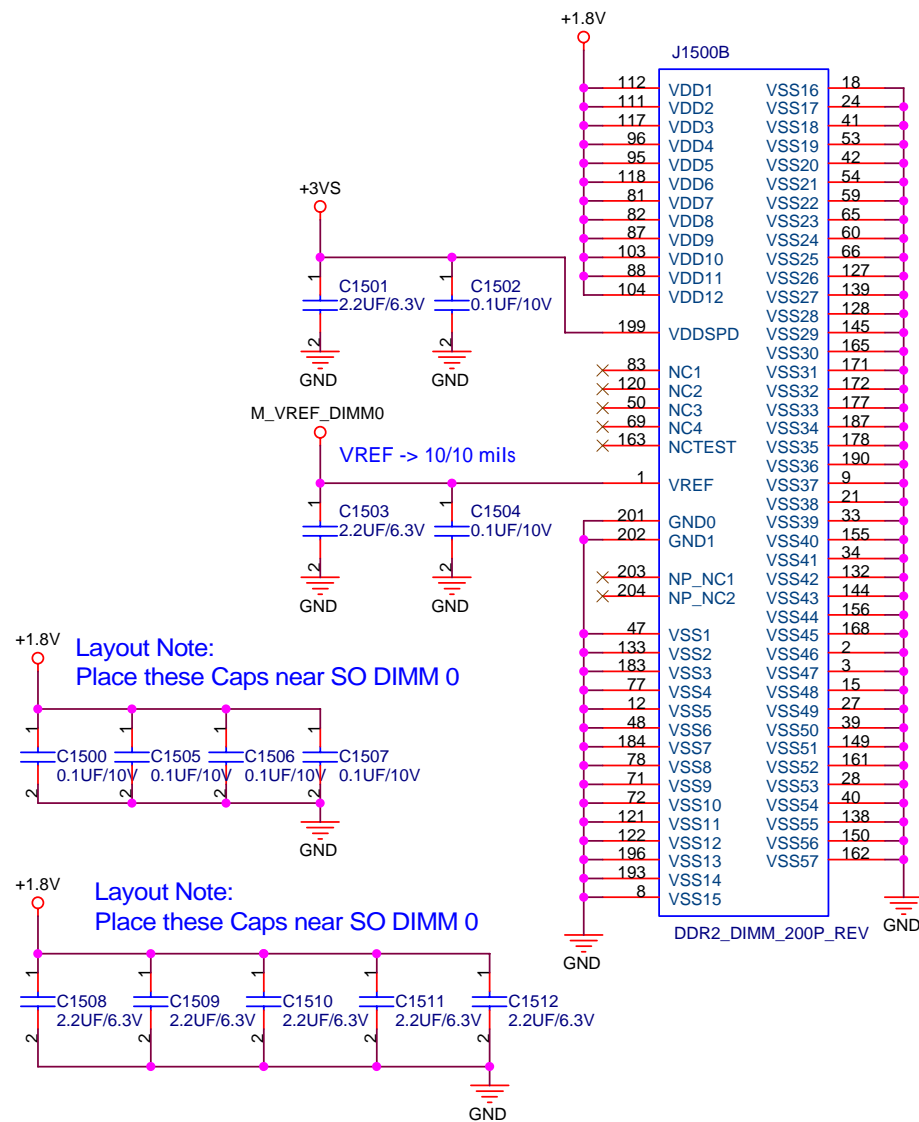
Group3

Group4

Group5

Group6

Group7



Title : DDR2 SO-DIMM(0)

ASUSTeK COMPUTER INC

Engineer: Ping-Yen Tsai

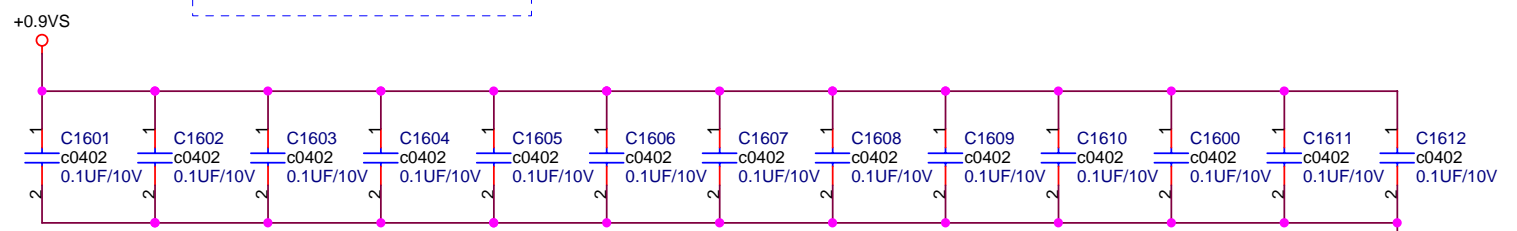
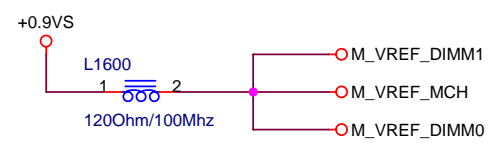
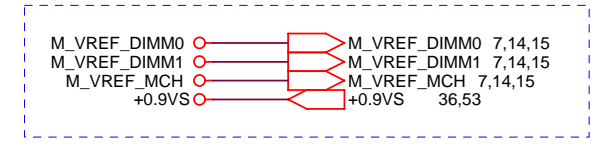
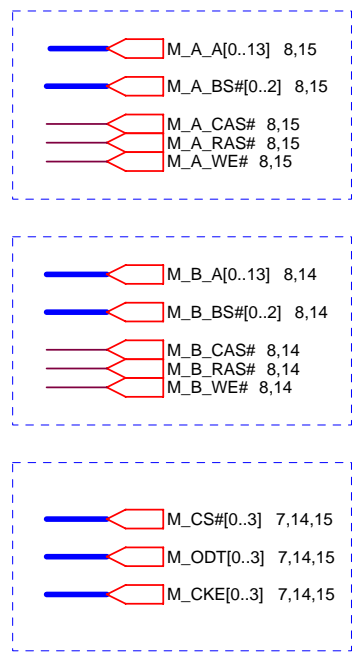
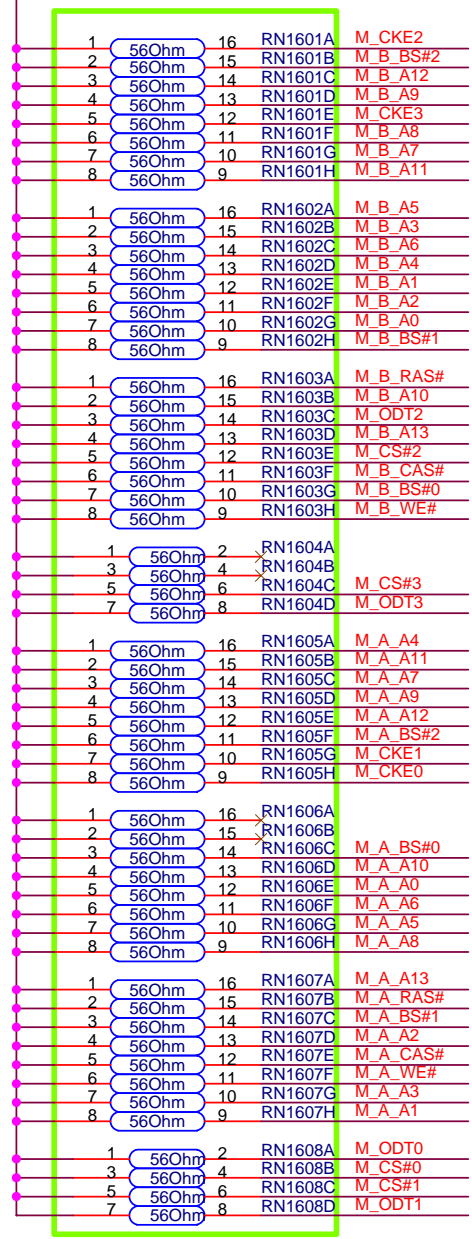
Size
A4Project Name
A3FRev
2.0

Date: Wednesday, January 18, 2006

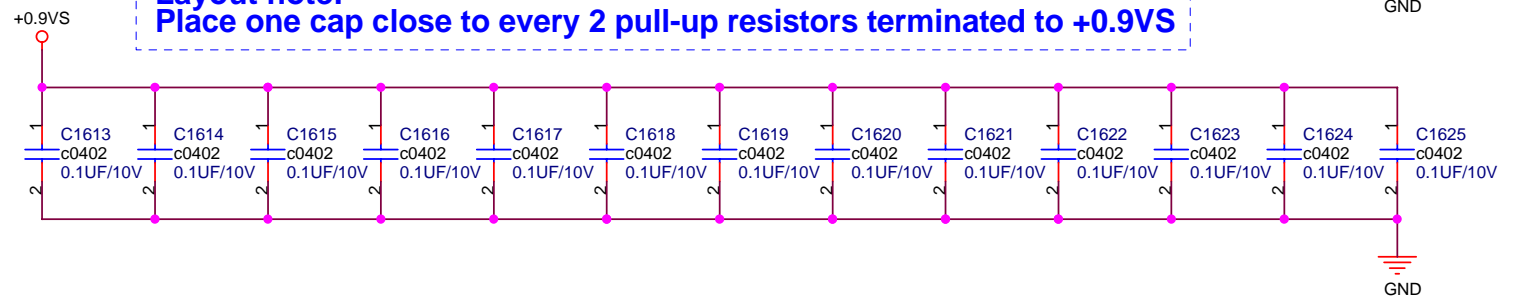
Sheet 15 of 63

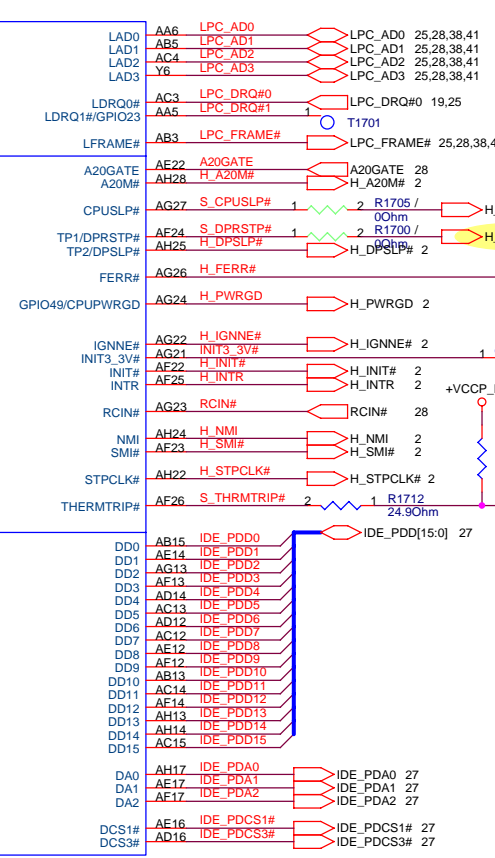
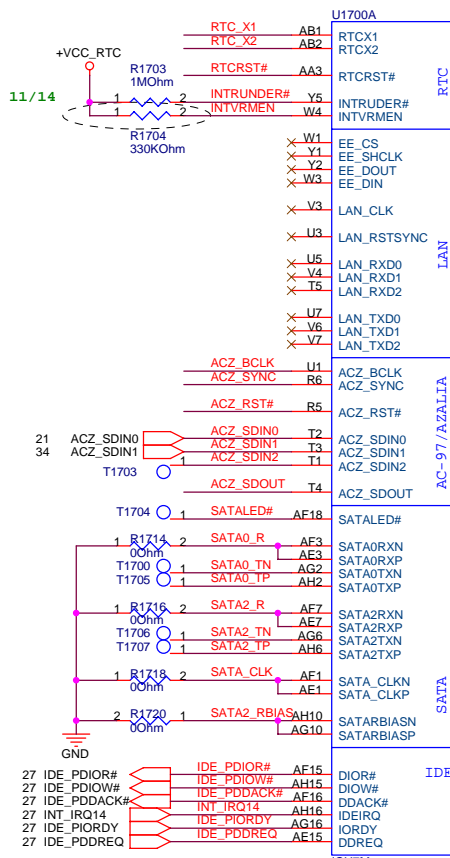
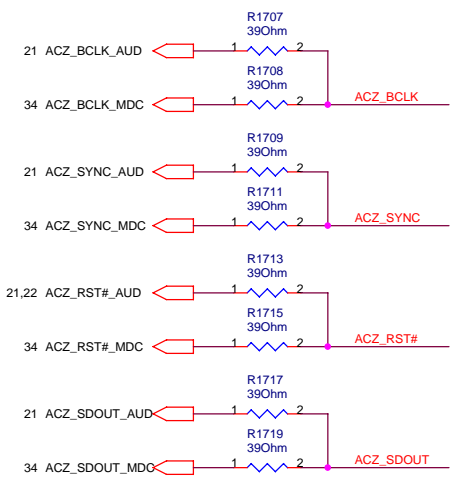
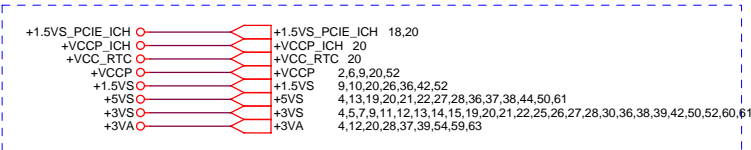
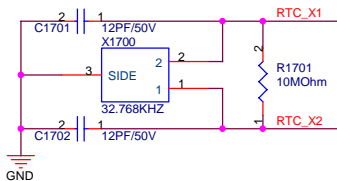
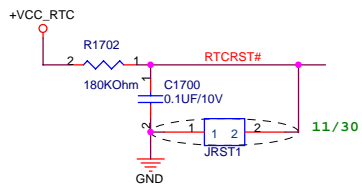
+0.9VS

NEED TO SWAP



Layout note:
Place one cap close to every 2 pull-up resistors terminated to +0.9VS





DPRSTP# routing from Intel 82801GBM to Yonah processor is required. Routing to VR must be done last and must have de-bounce filtering to handle daisy chain topology.

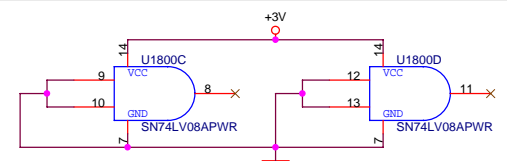
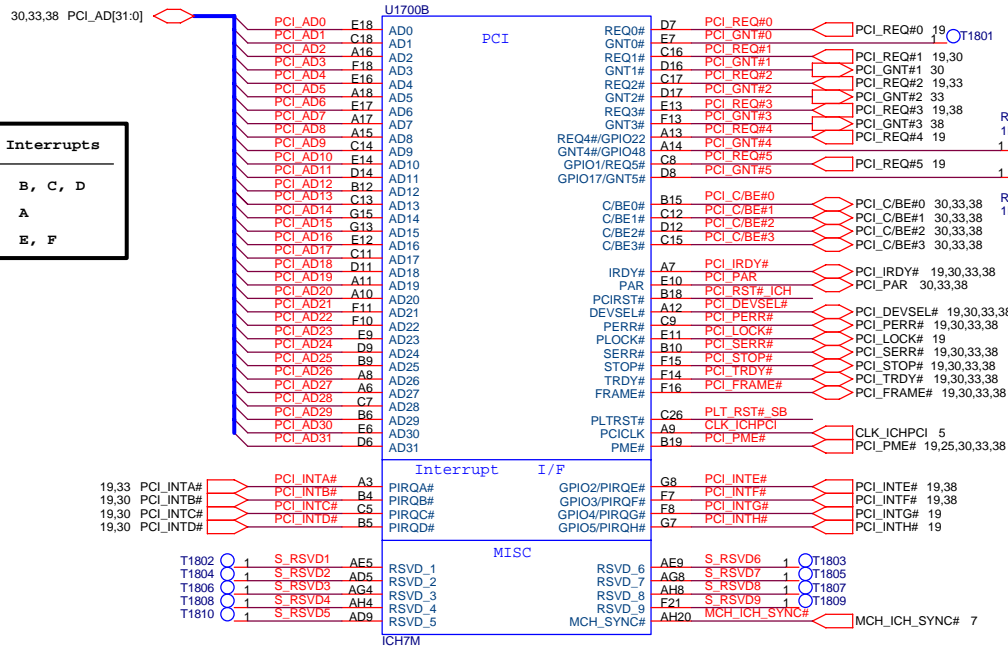
24 ± 5% series termination resistor placed within 2" from Intel 82801GBM, 56 ± 5% pull-up resistor has to be within 2" from the series resistor

ACZ_SDOUT	PWROK rising	TP3 pull low: allow entrance to XOR Chain testing TP3 not pull low: sets bit 1 of RPC.PC	PD
ACZ_SYNC	PWROK rising	sets bit 0 of RPC.PC	PD
EE_CS		should not be pulled high	PD
EE_DOUT		should not be pulled low	PU
GNT2#		should not be pulled low	PU
GNT3#	PWROK rising	low: "top-block swap" mode	PU
GNT5#/GPIO17# GNT4#/GPIO48	PWROK rising	GNT5# GNT4# 0 1 SPI 1 0 PCI 1 1 LPC	PU

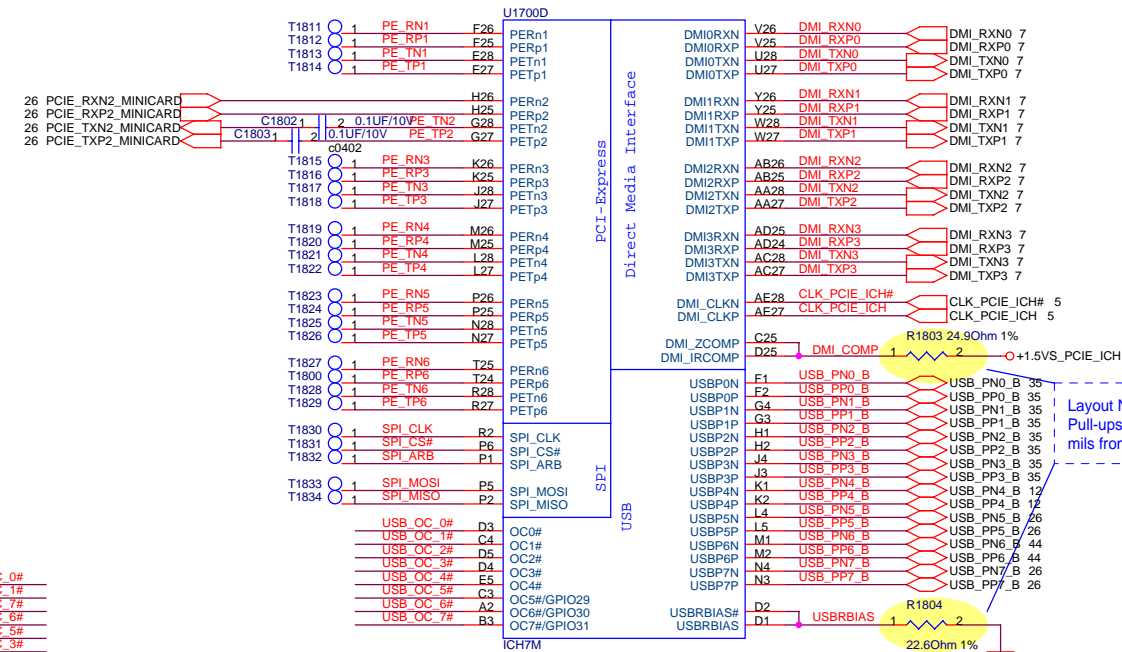
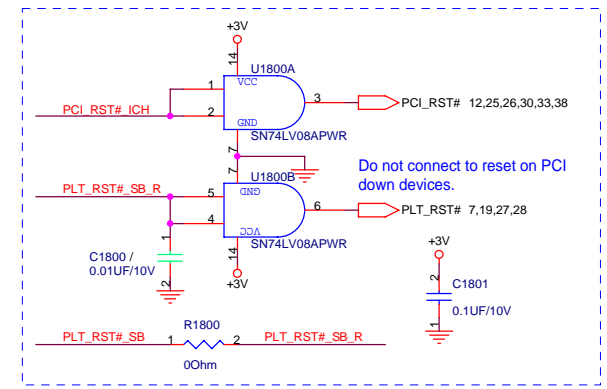
GPIO16 /DPRSTP#		should not be pulled high	PD
GPIO25	RSMRST# rising	should not be pulled low	PU
INTRVIRMEN	ALWAYS	high: Enable integrated Vccsusi_05 VRM	
LINKALERT#		REQUIRE an external pull-up R	Need
REQ[4:1]#	PWROK rising		PU
SATALED#		should not be pulled low	Conditional
SPKR	PWROK rising	high: "No reboot" mode	PD
TP3	PWROK rising	should not be pulled low unless using XOR Chain testing	PU

PCI Device

Device	IDSEL#	REQ#/GNT#	Interrupts
CardBus	AD17	REQ1#/GNT1#	B, C, D
LAN	AD23	REQ2#/GNT2#	A
Mini-PCI	AD19	REQ3#/GNT3#	E, F

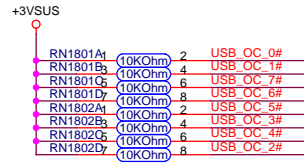


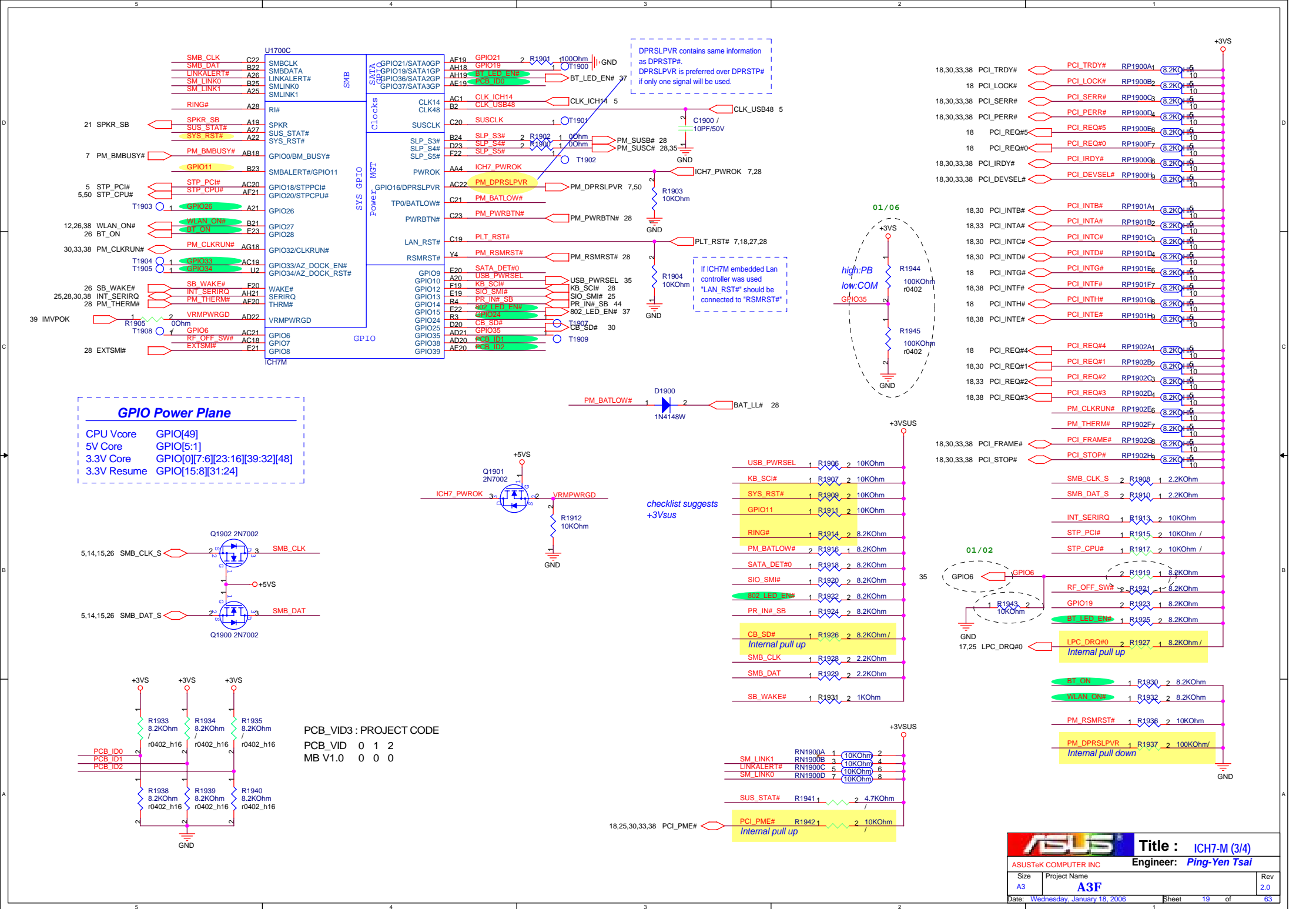
	LPC	PCI	SPI	GNT#5	GNT#4
	11	10	01	1	0
				(default)	

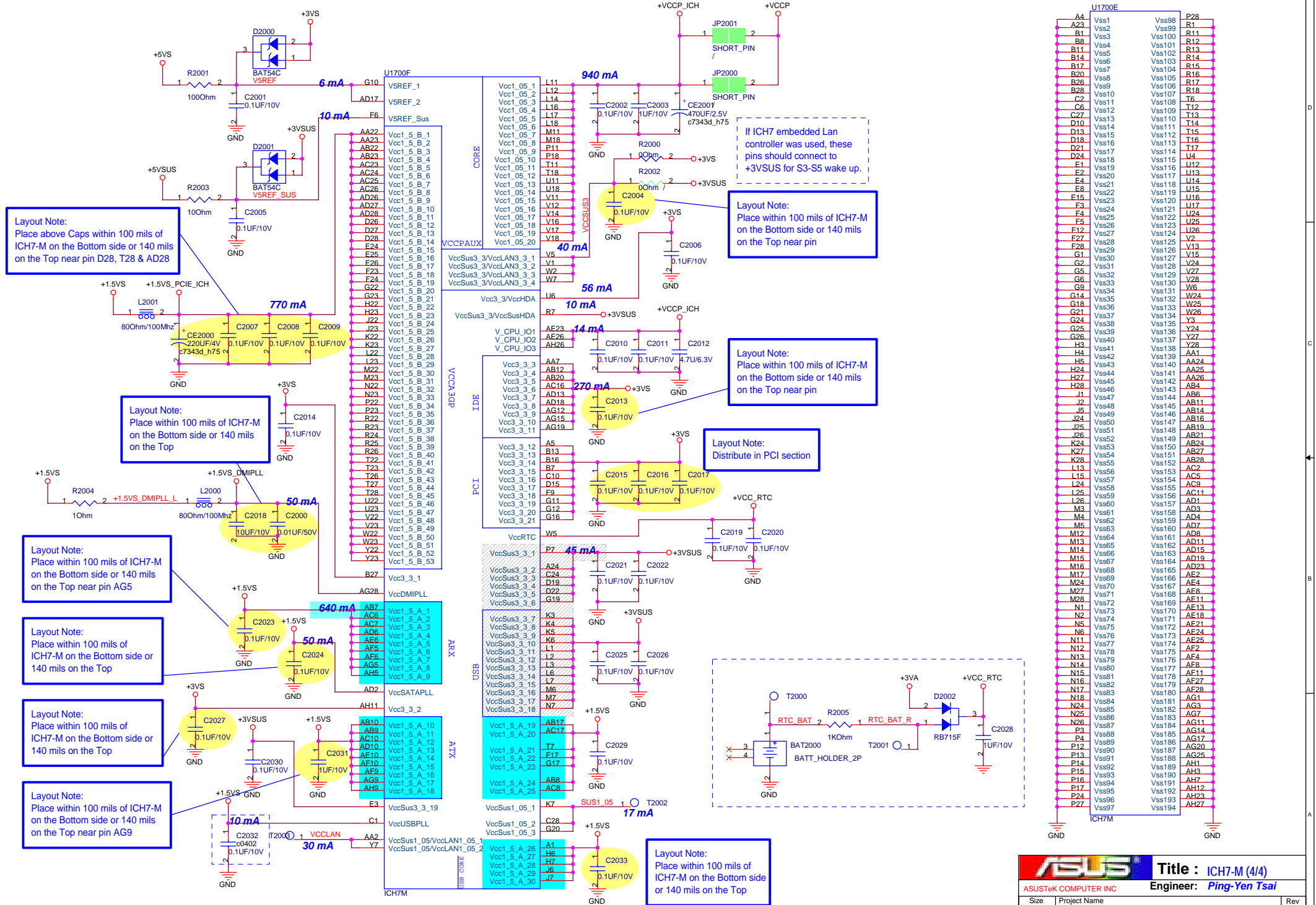


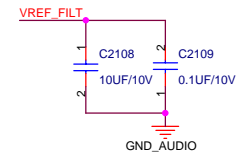
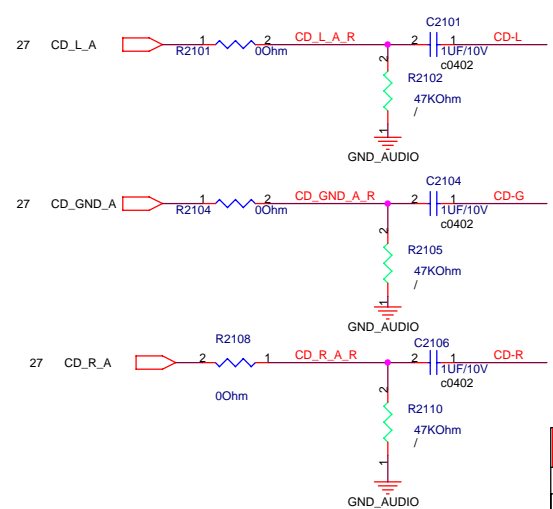
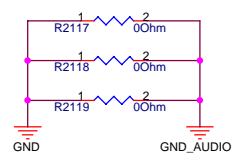
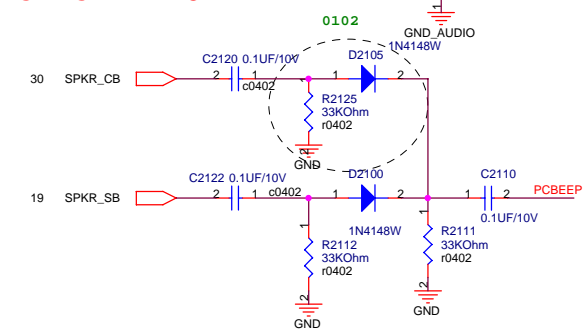
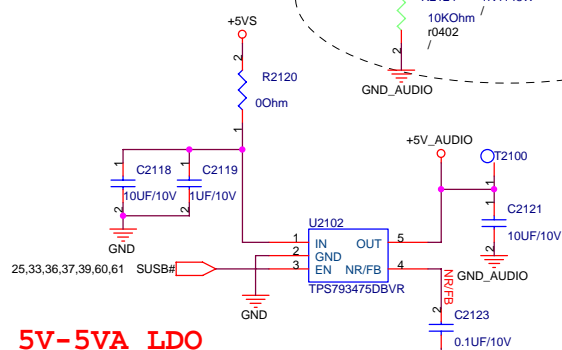
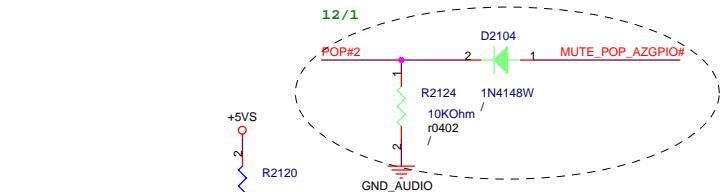
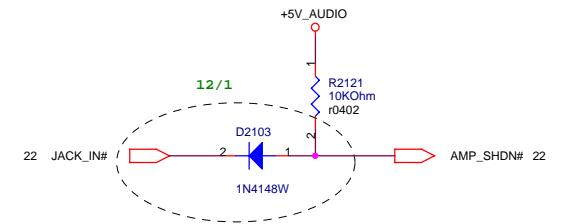
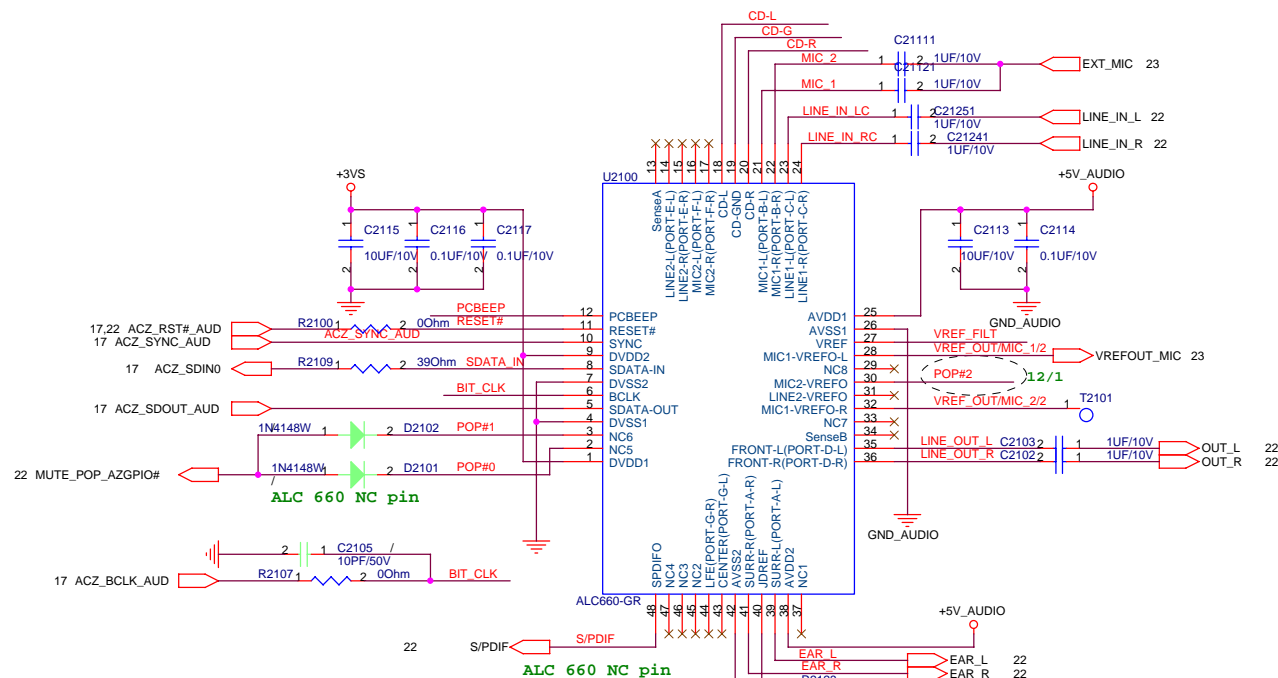
USB Devices

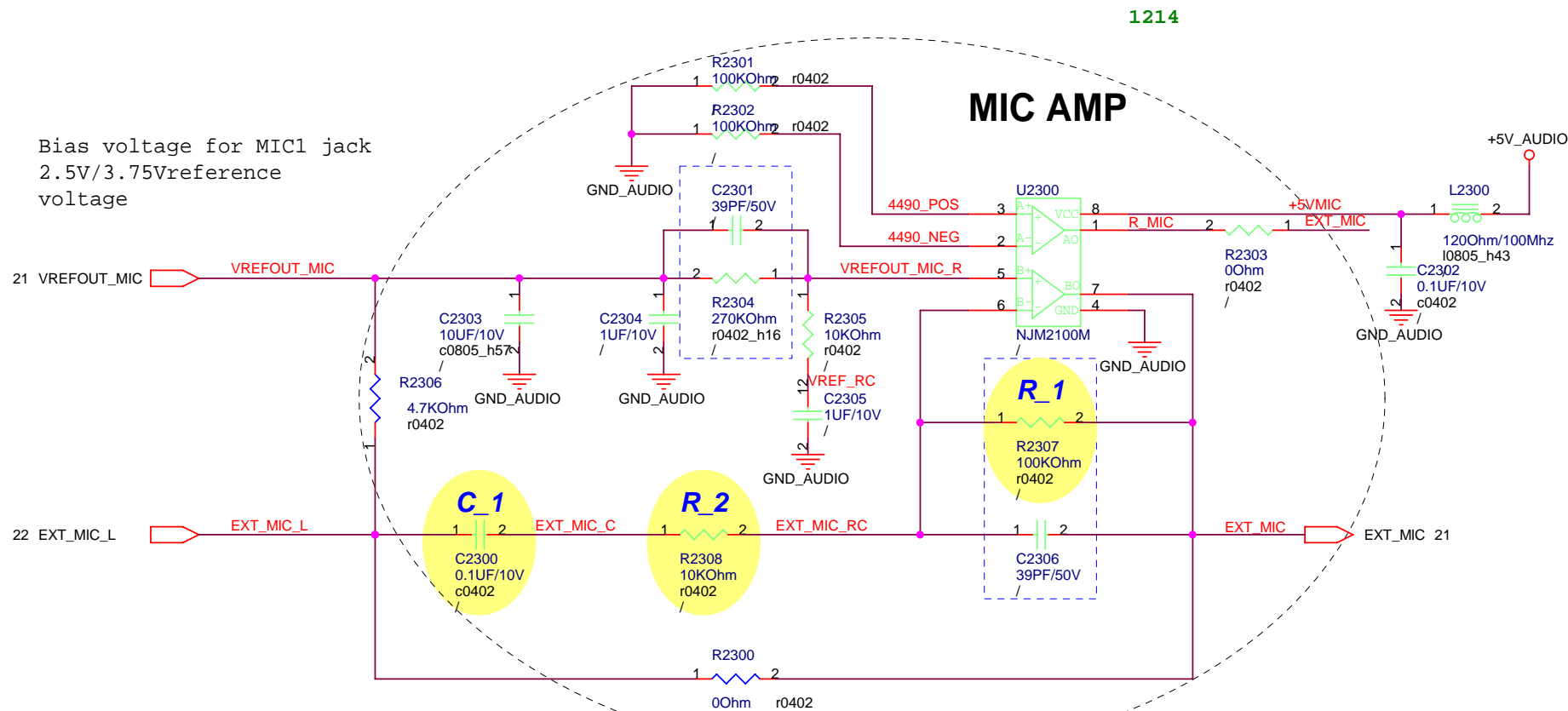
- Port 0 Conn. 0
- Port 1 Conn. 1
- Port 2 Conn. 2
- Port 3 Conn. 3
- Port 4 NC
- Port 5 Bluetooth
- Port 6 CMOS Camera
- Port 7 Mini Card





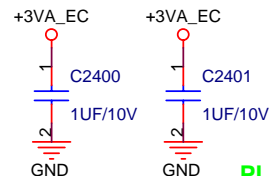






High-Pass Filter Cutoff Frequency
 $F_c = 1 / (2 \times 3.14 \times C_1 \times R_2) = 159 \text{ Hz}$

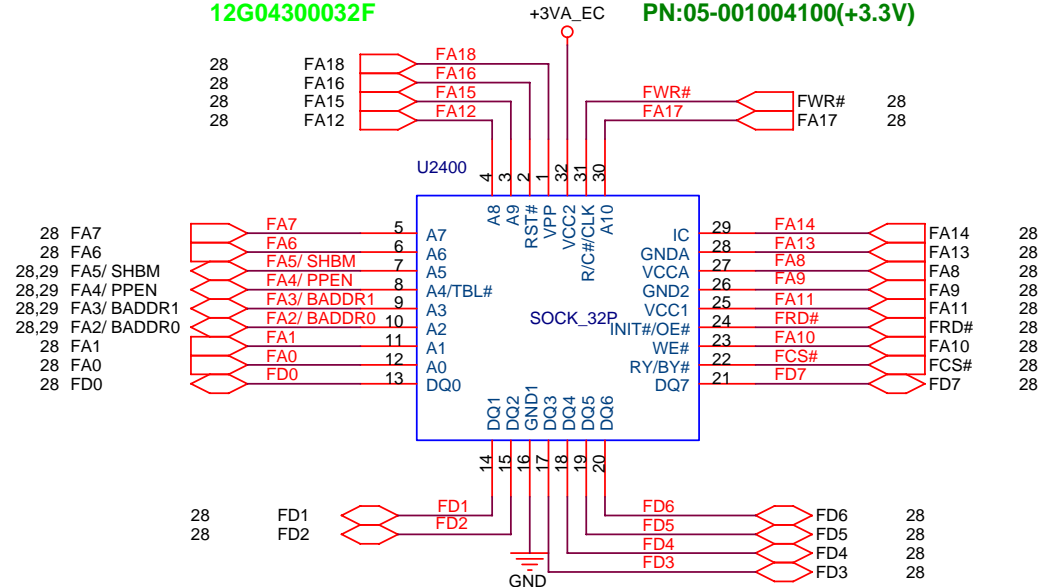
Gain = - R_1 / R_2 = -10



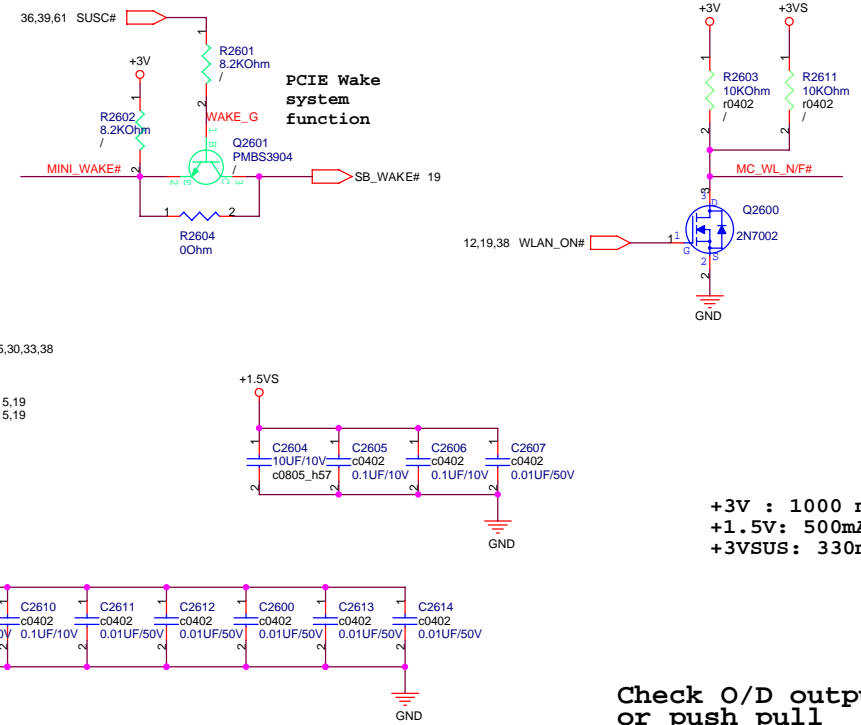
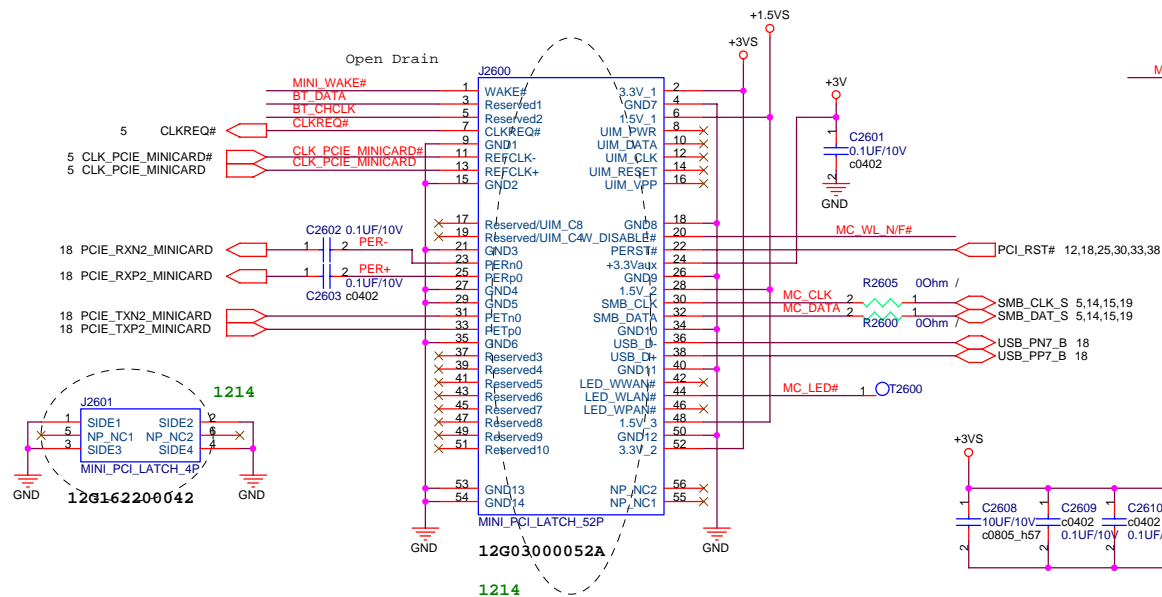
ISA ROM

PLCC32 Socket PN:
12G04300032F

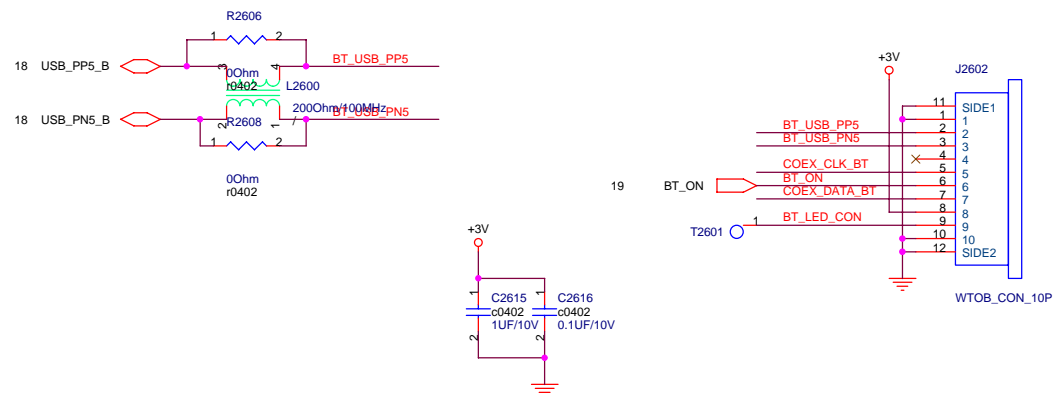
SST-PLCC32 4Mbits Flash ROM
PN:05-001004100(+3.3V)



MINI PCIEX CONNECTOR



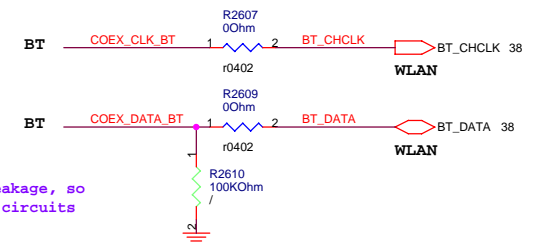
BLUETOOTH CONNECTOR

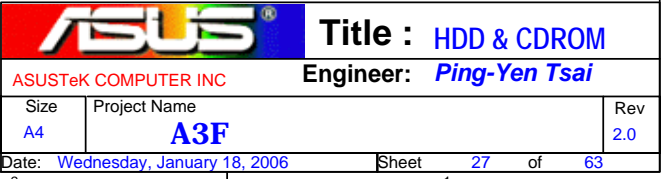


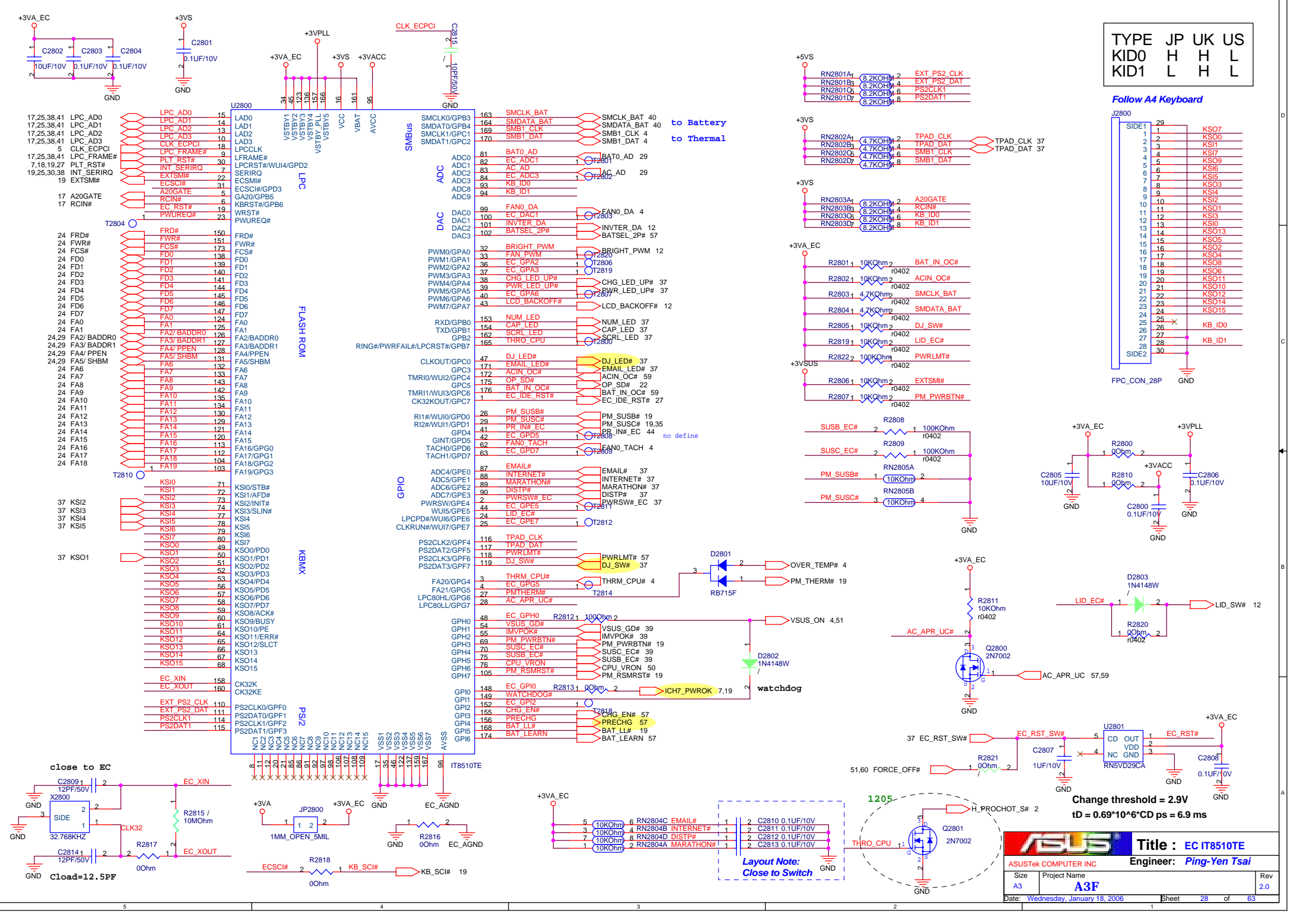
```
Signal direction-
CLK: BT -> WLAN;
DATA: WLAN -> BT
```

```
BT_ON 3.3V at
GPIO38
```

BT Module has no leakage, so
discard PMOS block circuits

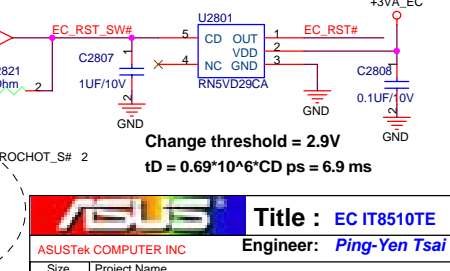
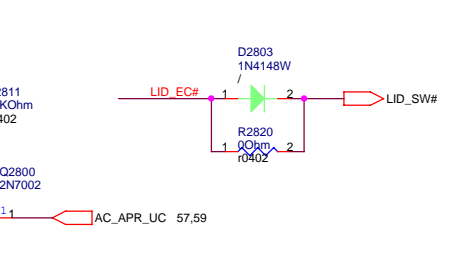
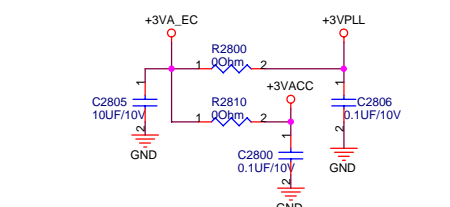
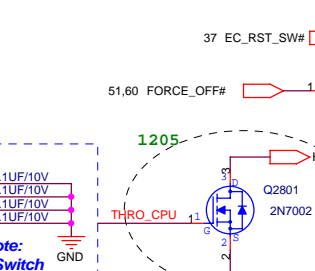
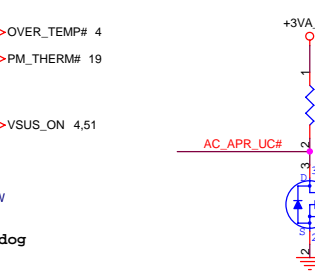
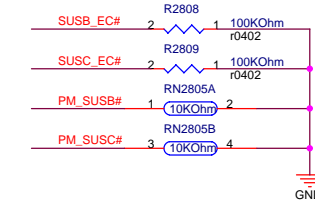
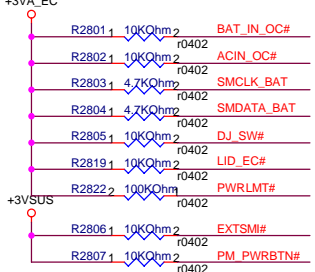
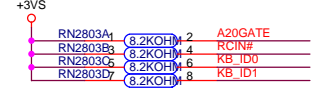
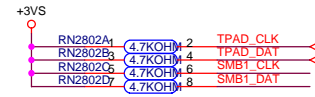
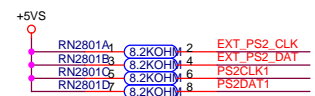
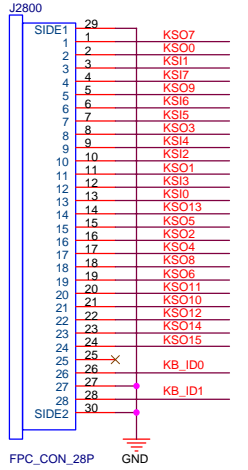






TYPE	JP	UK	US
KID0	H	H	L
KID1	L	H	L

Follow A4 Keyboard



Title : EC IT8510TE
ASUSTek COMPUTER INC
Engineer: Ping-Yen Tsai
Size: A3 Project Name: A3F
Date: Wednesday, January 18, 2006 Sheet 28 of 63

to Battery
to Thermal

no define

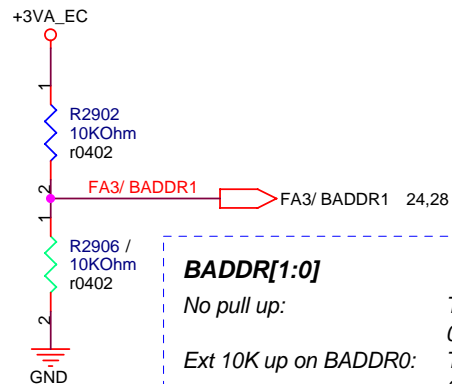
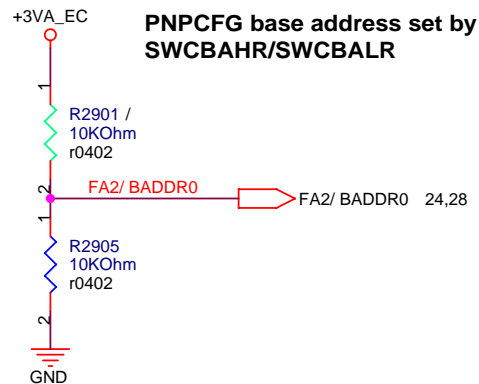
watchdog

Layout Note:
Close to Switch

Change threshold = 2.9V
tD = 0.69*10^6 CD ps = 6.9 ms

EC Hardware Strap

Strap value sampled after
VSTBY power up reset



BADDR[1:0]

No pull up:

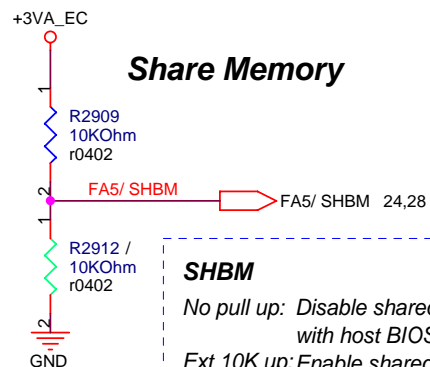
Ext 10K up on BADDR0:

Ext 10K up on BADDR1:

The register pair to access PNPCFG is 002Eh and 002Fh.

The register pair to access PNPCFG is 004Eh and 004Fh.

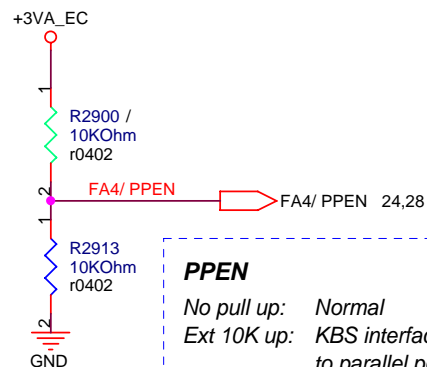
The register pair to access PNPCFG is determined by EC domain registers SWCBALR and SWCBAHR.



SHBM

No pull up: Disable shared memory with host BIOS

Ext 10K up: Enable shared memory with host BIOS



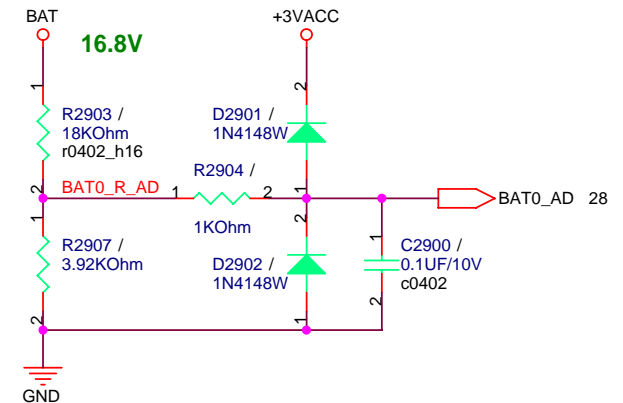
PPEN

No pull up: Normal

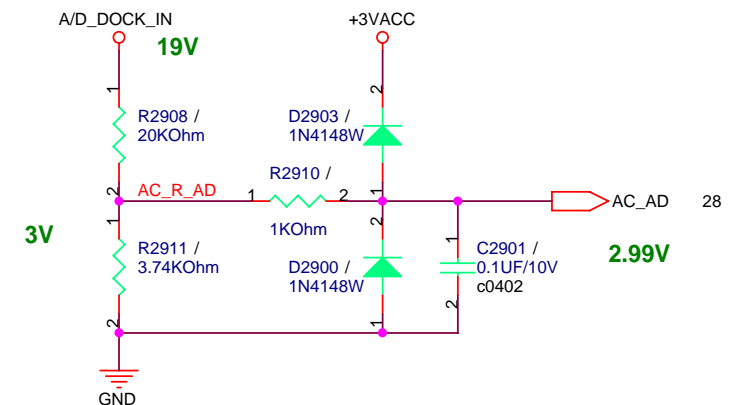
Ext 10K up: KBS interface pins are switched to parallel port interface for in-system programming.

EC ADC

Battery



Adaptor



Title : EC IT8510TE(2/2)

ASUSTek COMPUTER INC

Engineer: Ping-Yen Tsai

Size
A4

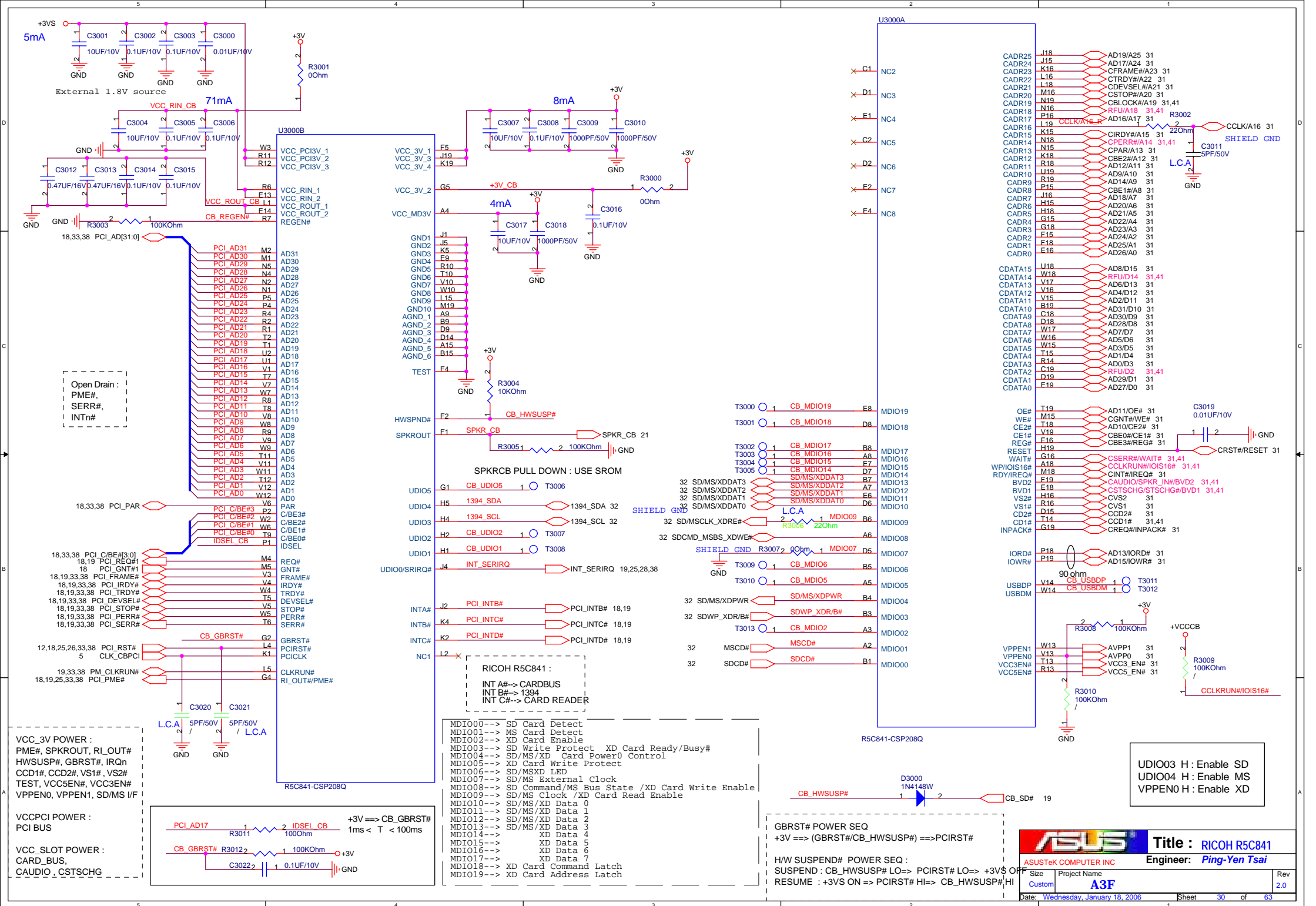
Project Name

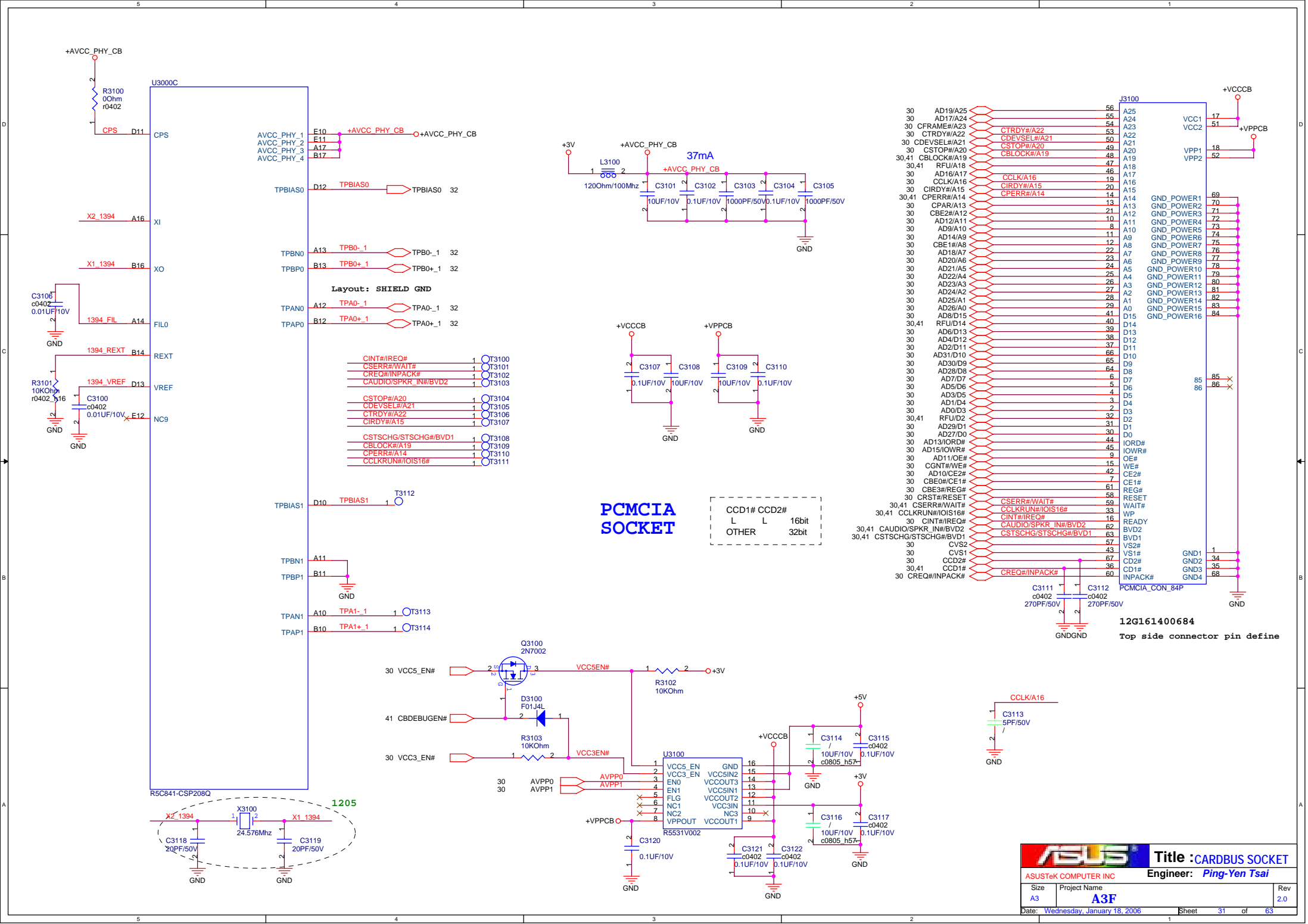
A3F

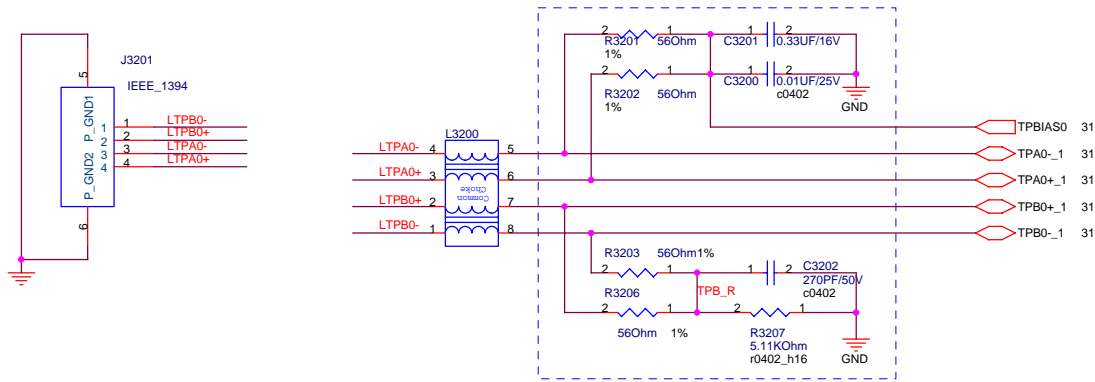
Rev
2.0

Date: Wednesday, January 18, 2006

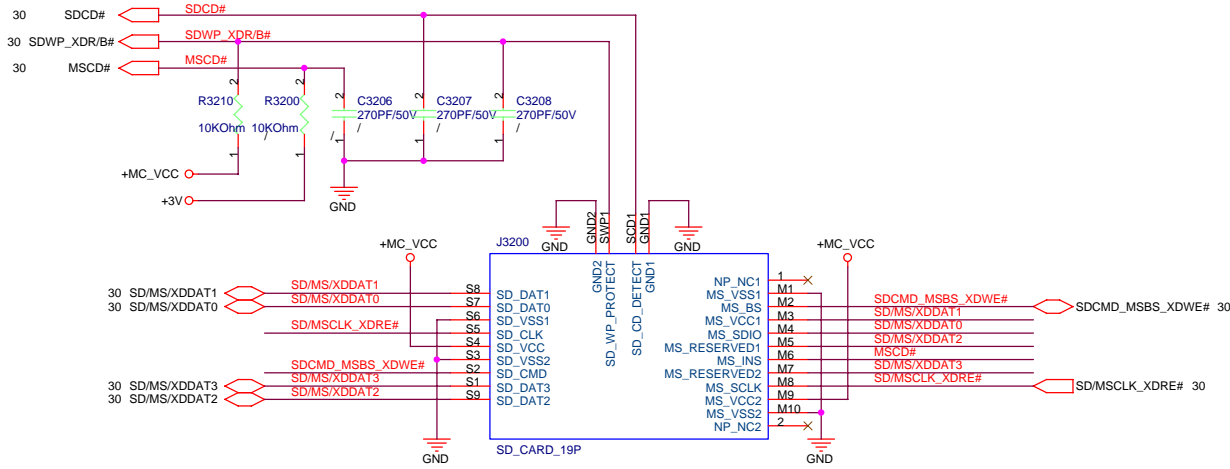
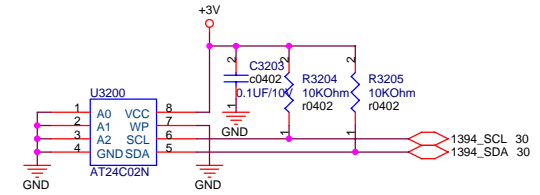
Sheet 29 of 63



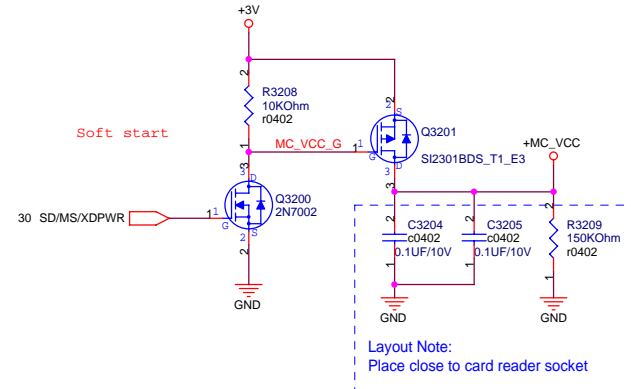




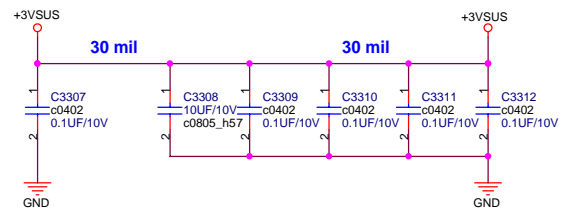
1. Close to R5C841
2. The area is as compact as possible, length < 10 mm
3. TPA Pair and TPB pair mismatch < 2.5mm
4. No via recommend, maximum is one.
5. Total length < 50 mm
6. Differential impedance is 110+/- 6 ohm
7. TPA Pair trace or TPB pair trace mismatch < 1.25mm



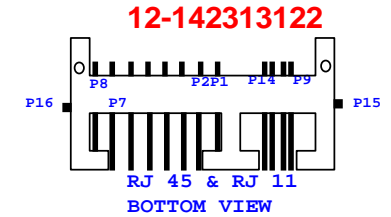
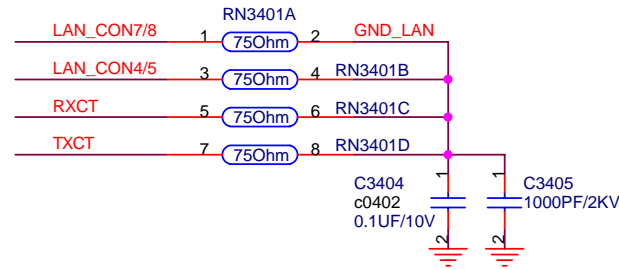
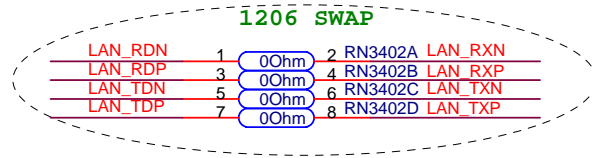
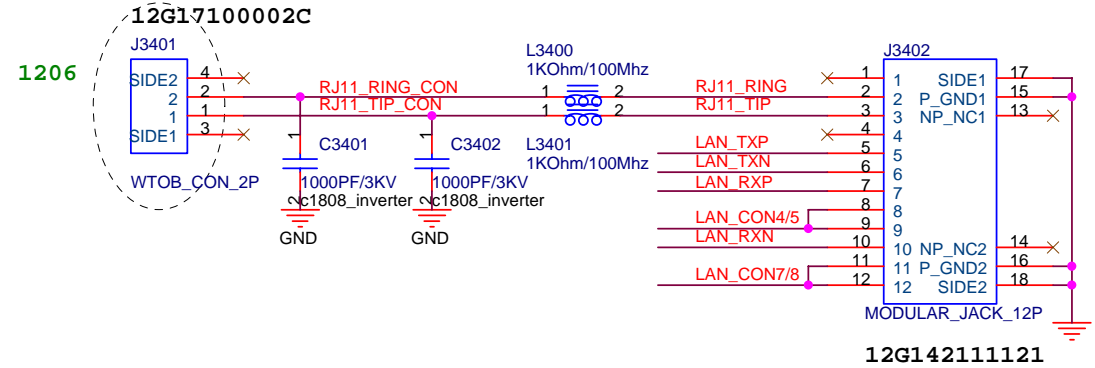
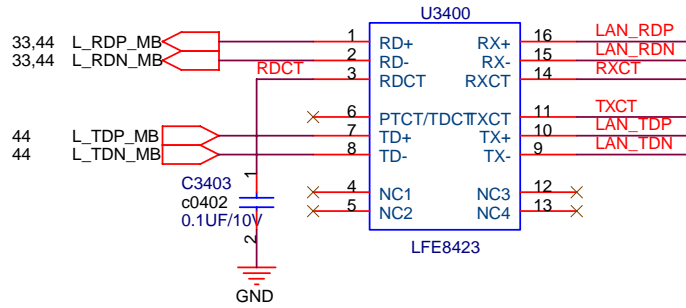
Layout: SHIELD GND



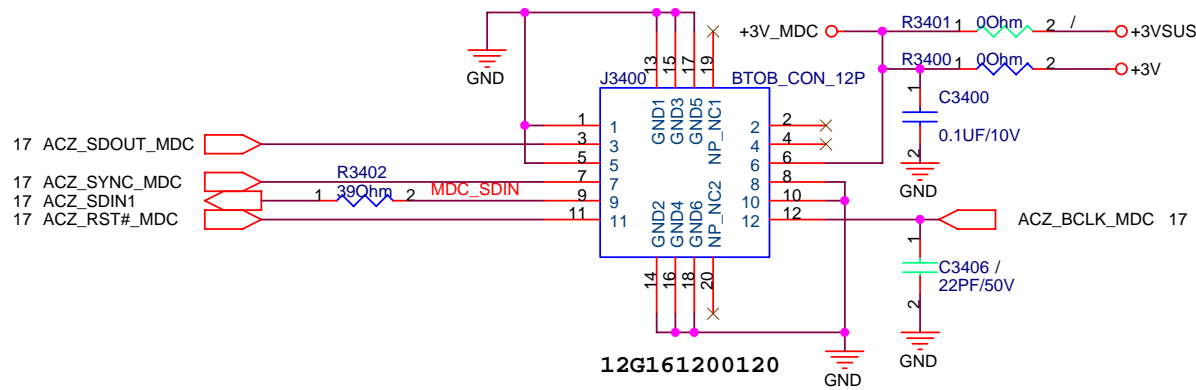
Layout Note:
Place close to card reader socket

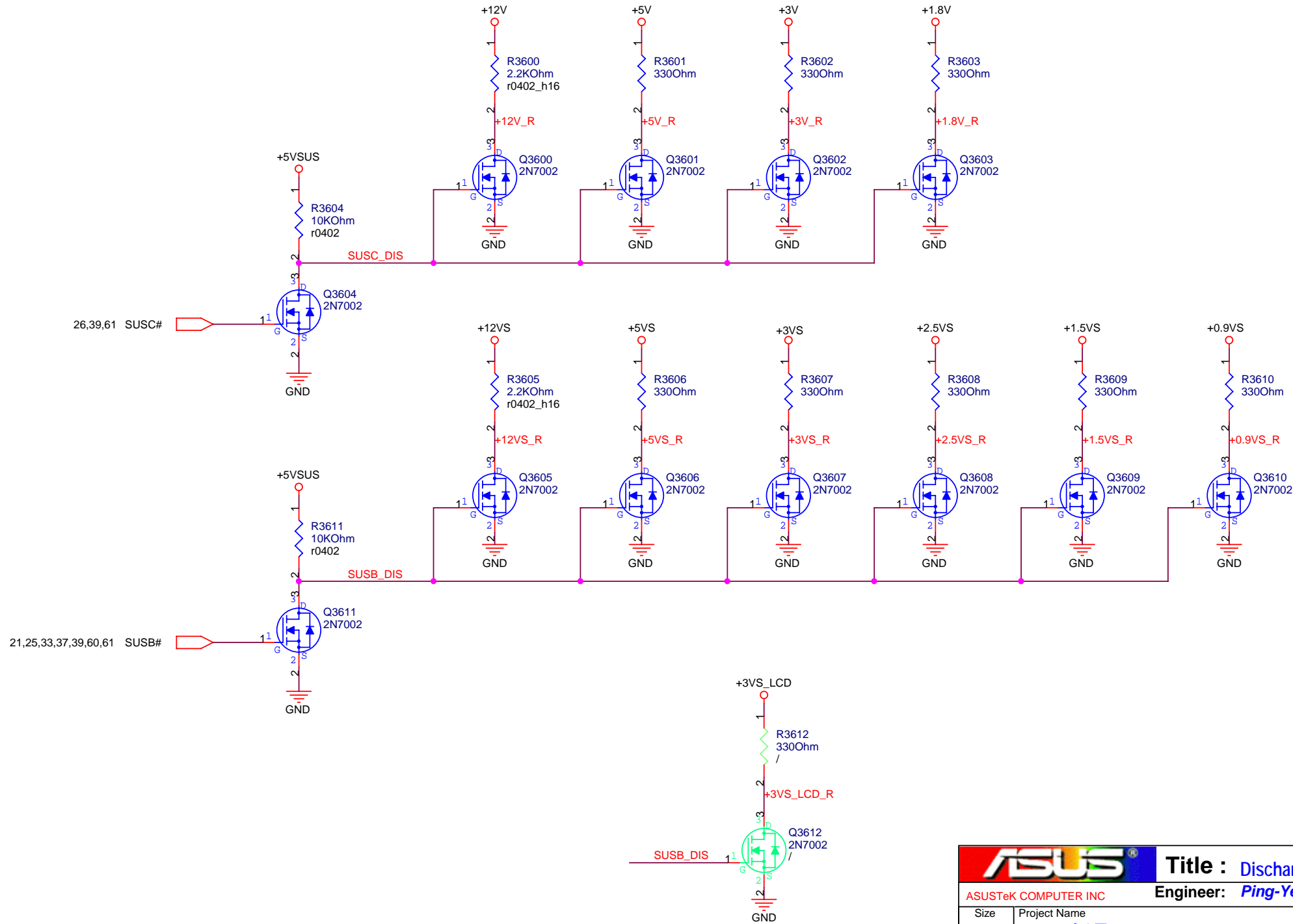


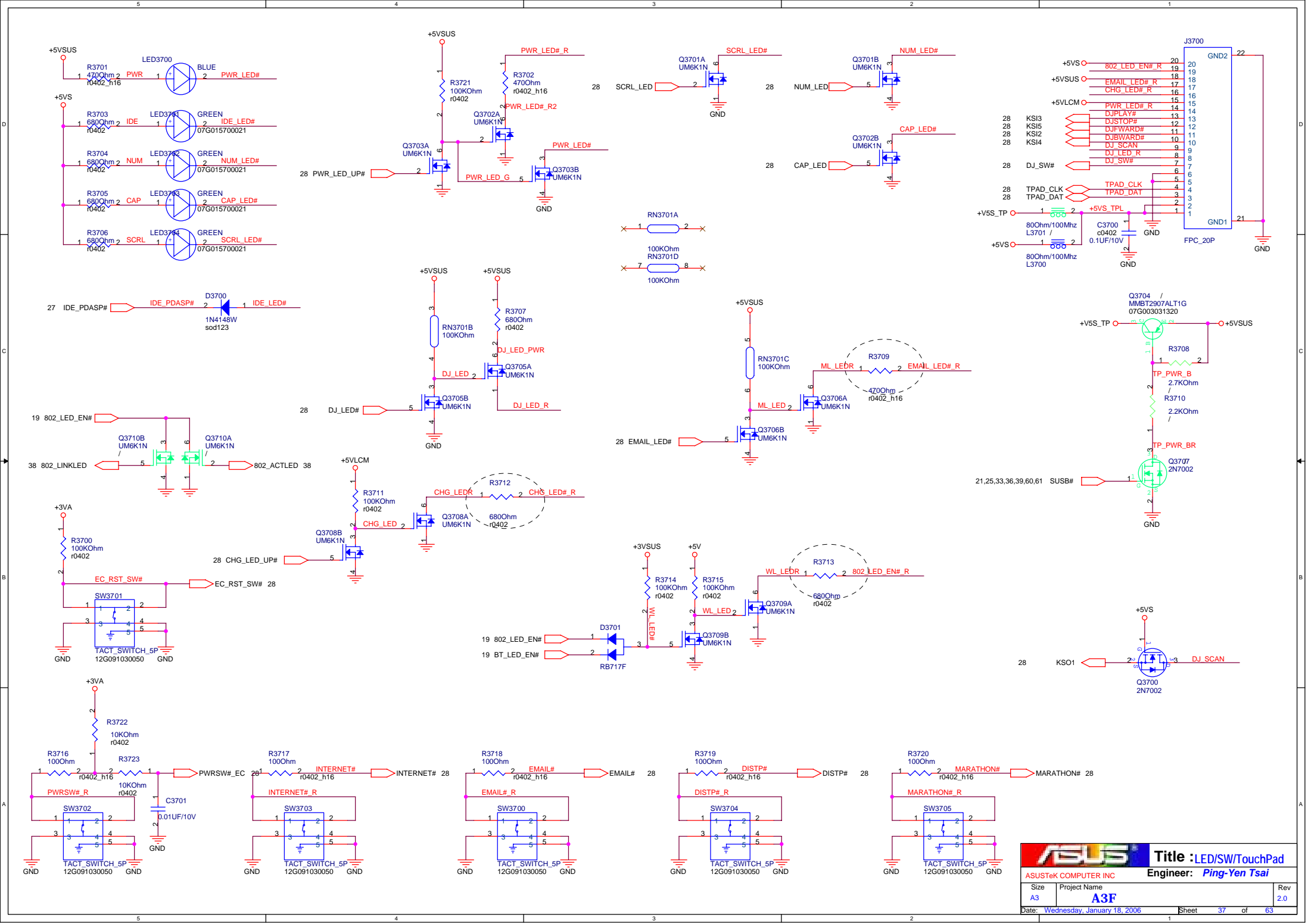
LAN PORT

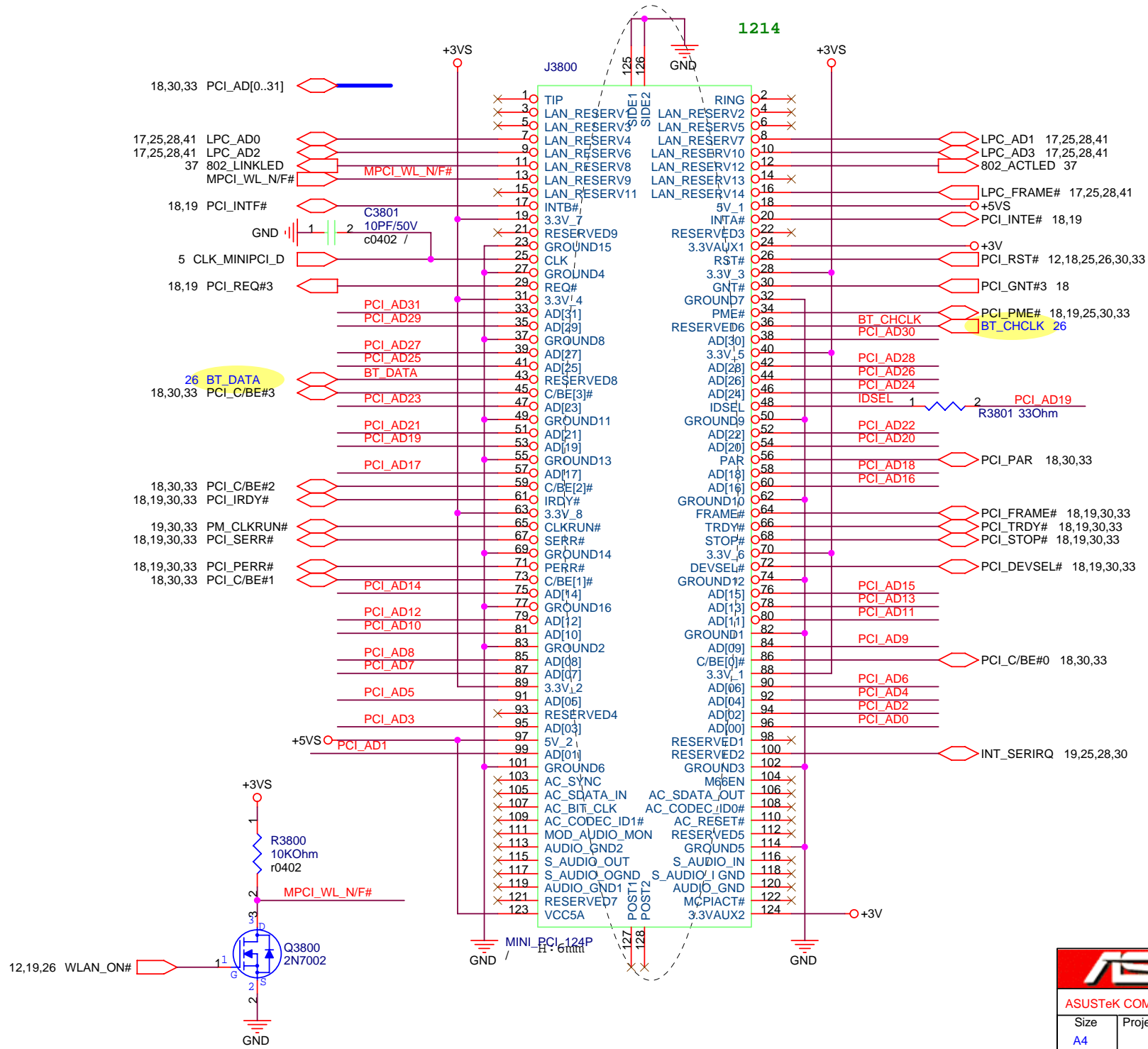



MDC Conn







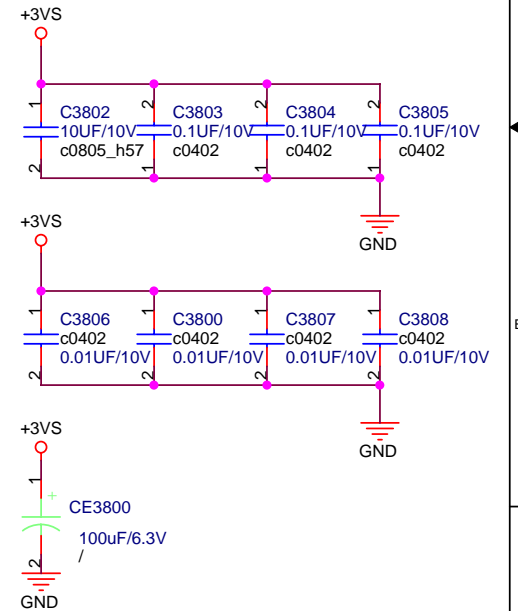


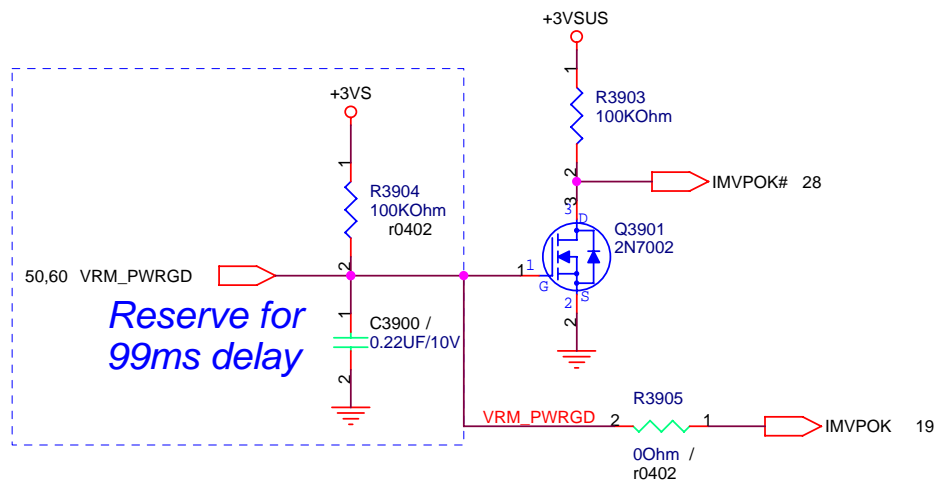
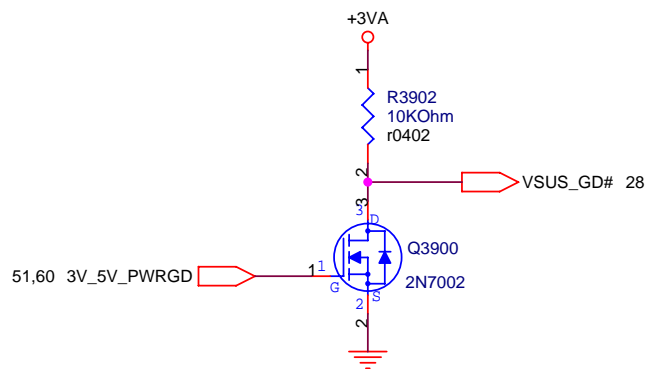
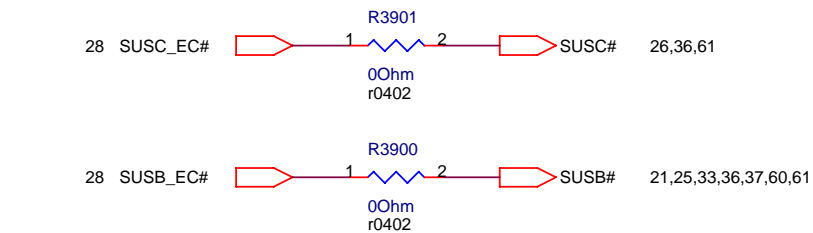


Title : MINIPCI (802.11)

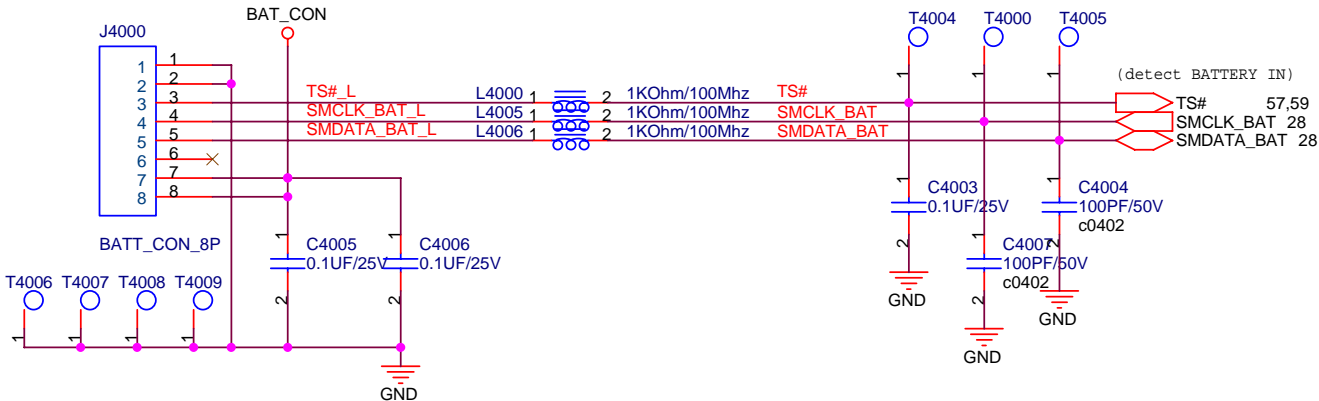
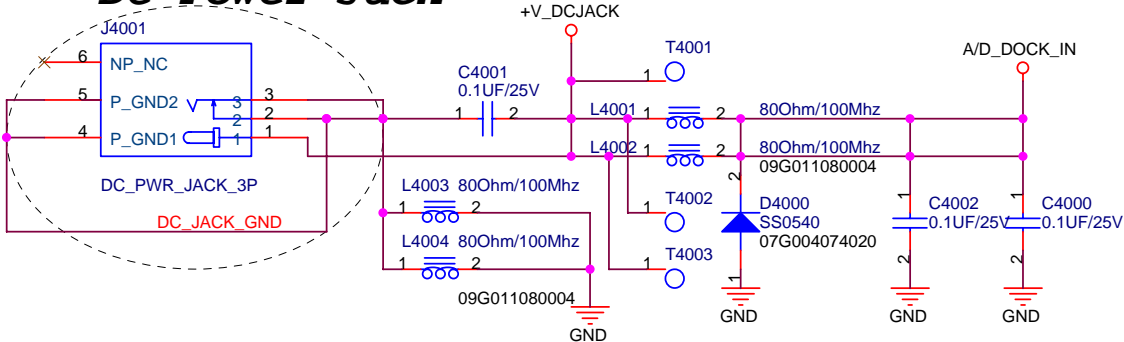
Engineer: Ping-Yen Tsai

Size	Project Name	Rev
A4	A3E	2.0
Date: Wednesday, January 18, 2006		Sheet 38 of 63



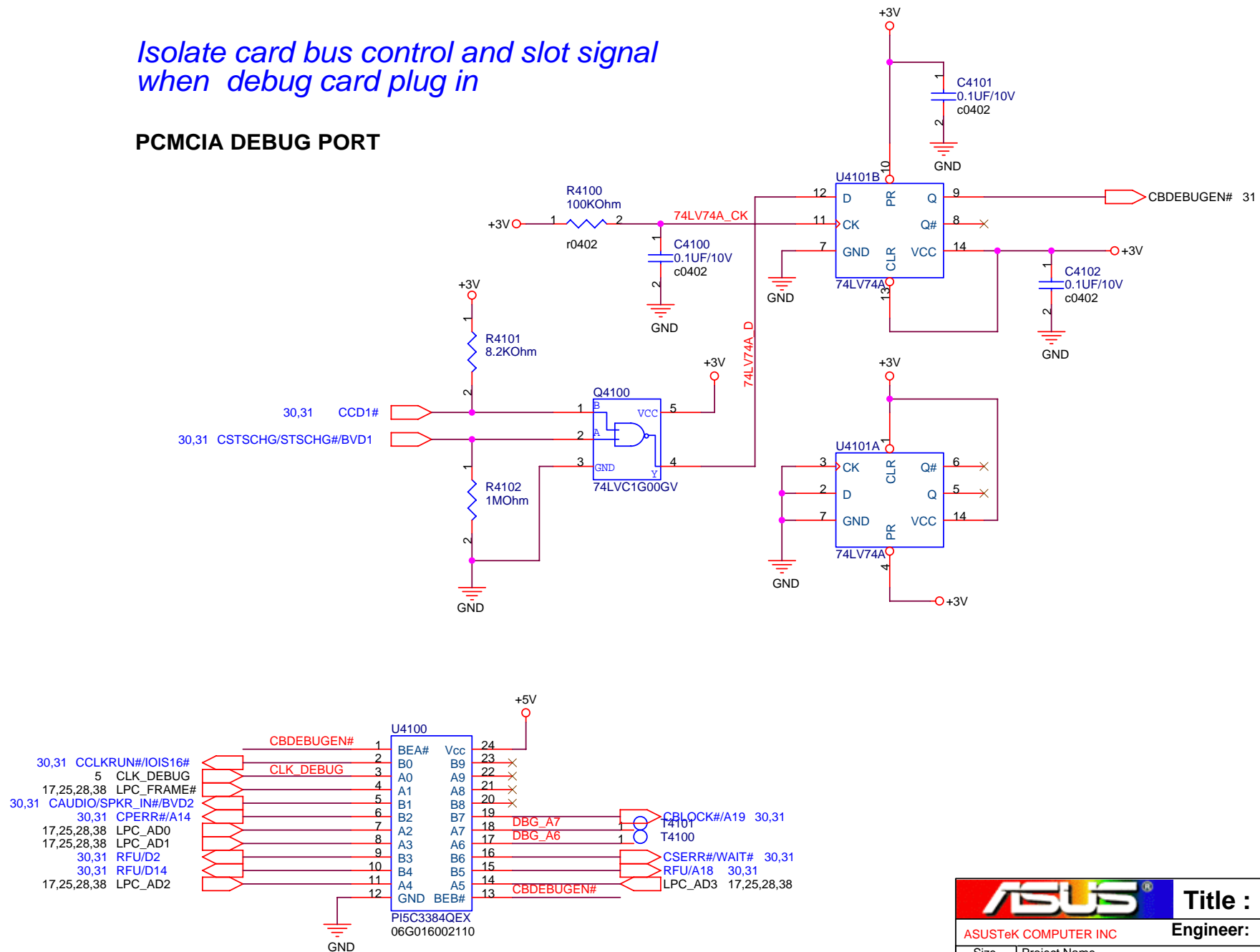


DC Power Jack

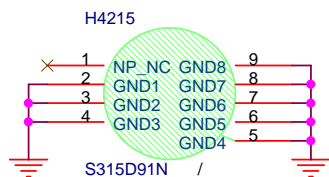
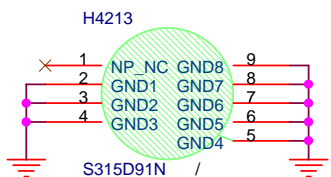
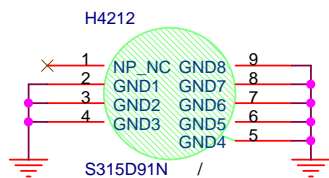
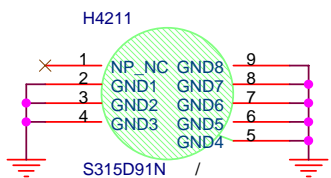
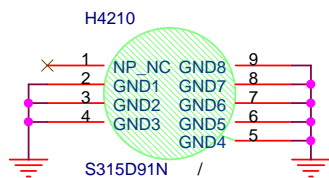
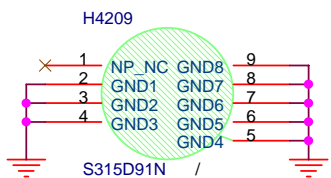
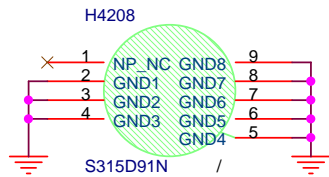
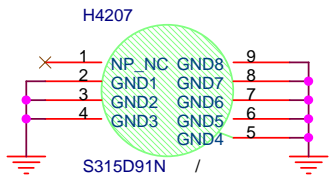
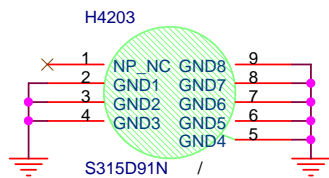
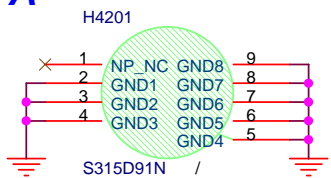


*Isolate card bus control and slot signal
when debug card plug in*

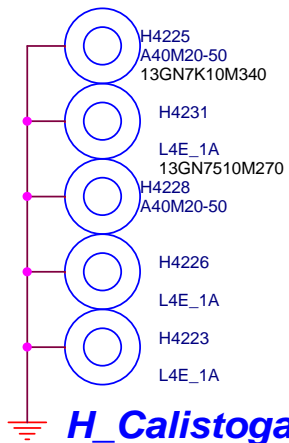
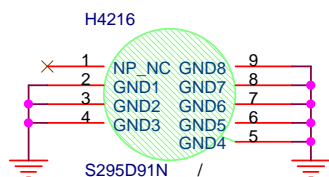
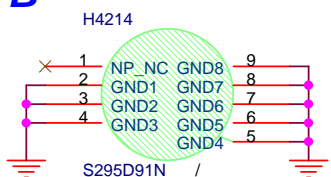
PCMCIA DEBUG PORT



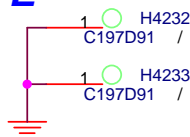
A



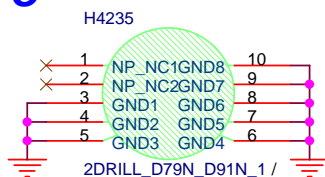
B



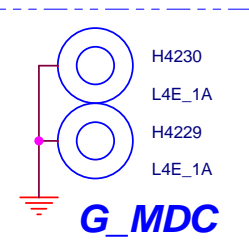
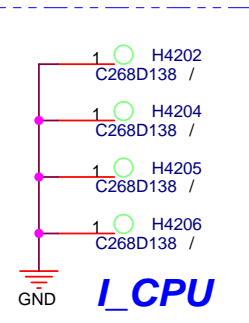
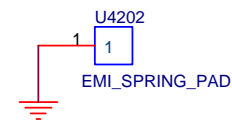
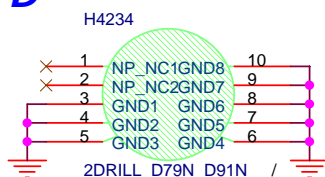
E



C



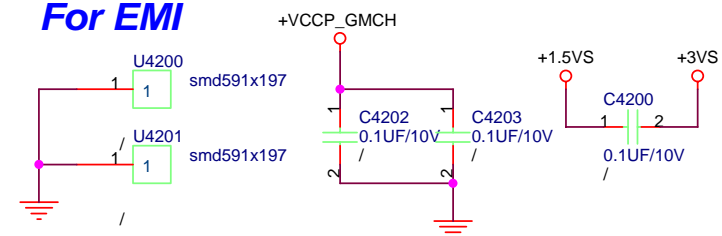
D



J



For EMI



ASUS		Title : SCREW HOLE	
ASUSTeK COMPUTER INC		Engineer: Ping-Yen Tsai	
Size A4	Project Name A3F		Rev 2.0
Date: Wednesday, January 18, 2006		Sheet 42 of 63	

R1.1

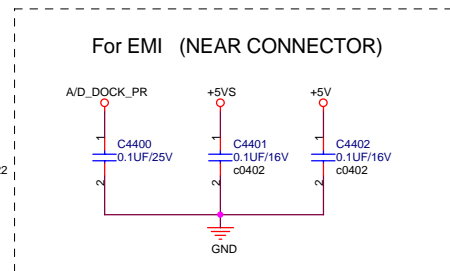
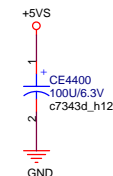
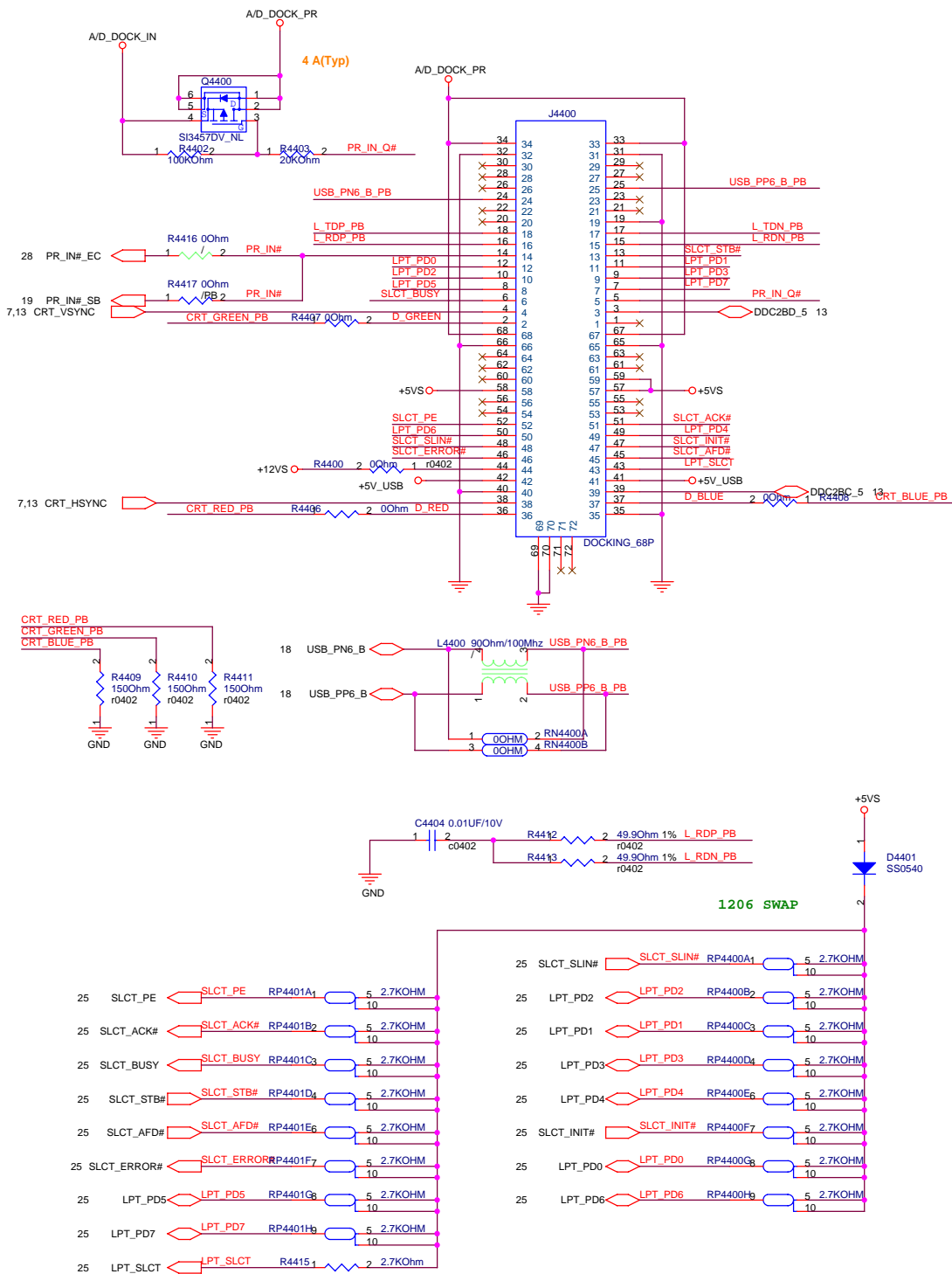
- 11/14 1. Change resistor number from R1 to R1401
2. Change R1704 value from 10K to 330K
3. Add U2202 C D E F
4. Change C2511 value from 0.1uF to 0.047uF(11G232147316360)
5. Change C2510, C2514 and C2515 value from 0.1uF to 0.33uF(11G232333436030)
- 11/29 1. Remove R409
2. USB port (J3500) power control on shutdown of AC mode
3. Change U2202 power source form "+3VS" to "+3V" to solve pop noise
4. Add D2202 1N 4148W P/N 07G001001612 to solve pop noise when power off
5. Remove R2201 and mount R2203 to change Gain Setting
- 12/1 1. Change component D2103 DAP202K to 1N4148W P/N 07G001001612
2. Add Components 10K Ohm & 1N4148W P/N 07G001001612 and connect U2100 pin 30
3. Change J1500,U900,U2502,U3400,H4225,H4226,H4228,H4229,H4230,H4223,H4231,Q4400 to green part
- 12/2 1. Change Thermal Sensor to SO-8 MAX6657
2. USB4-->Camera, USB6-->PB
- 12/5 1.Change material CE1200, F3500, F3501, F3502
2. Add EC new function-->THRO_CPU
3. Change X3100, C3118, C3119 J3401 part number
- 12/7 1.Change J2500 footprint
- 12/9 1.Change R1202 value

R2.0

- 1/2 1. BOM Add R1943, Remove R1919
2. BOM Add D2105, R2125
3. BOM Add C2223
4. BOM Add R3505, Q3505, U3500
5. Schematics Add R3503, R3504 but don't mount
6. Schematics Add R4418~R4424 but don't mount
- 1/4 1. change R3709, R3712 & R3713 value
- 1/6 1. Add Power schematics & GPIO35 (Add R1944,R1945)

- 1/9 1. Remove JP3500, Add R3506, R3507
- 1/10 1. Add R415, BOM remove R408 Q403
- 1/11 1. Change C404 to 0.47uF
2. Change DJ JACK part number

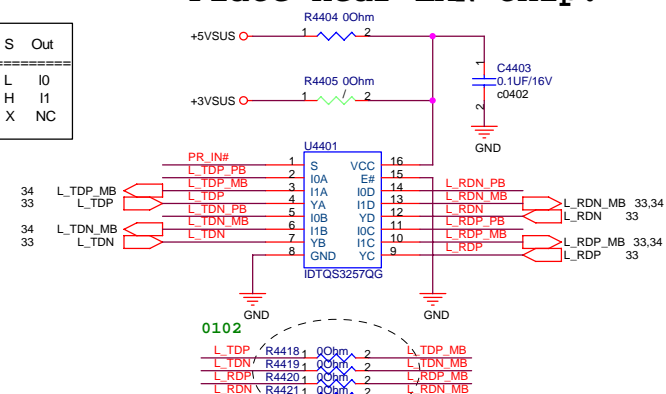
		Title : HISTORY	
ASUSTeK COMPUTER INC		Engineer: Ping-Yen Tsai	
Size Custom	Project Name A3F		Rev 2.0
Date: Wednesday, January 18, 2006		Sheet	43 of 63



LAN Switch

OE	S	Out
L	L	I0
L	H	I1
H	X	NC

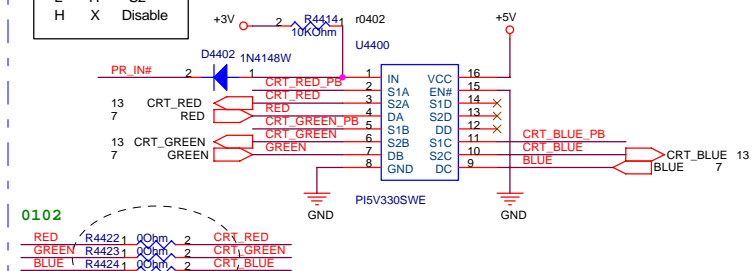
Place near LAN chip!



CRT Switch

OE#	IN	Out
L	L	S1
L	H	S2
H	X	Disable

Place near Calistoga !



1

1

8

A

5

4

3

2

1

1

8

A

5

4

3

2

Title

<Title>

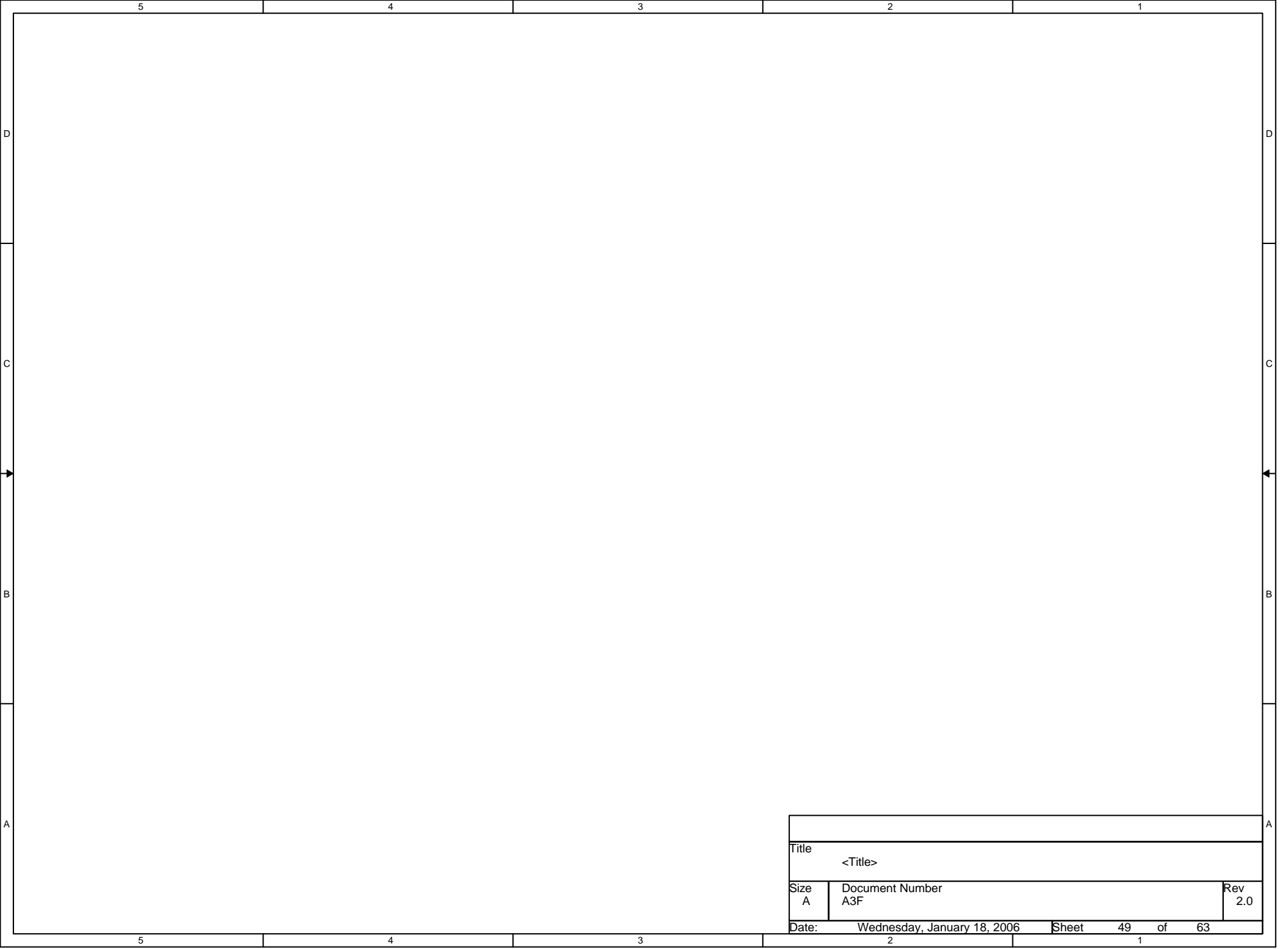
Size
A

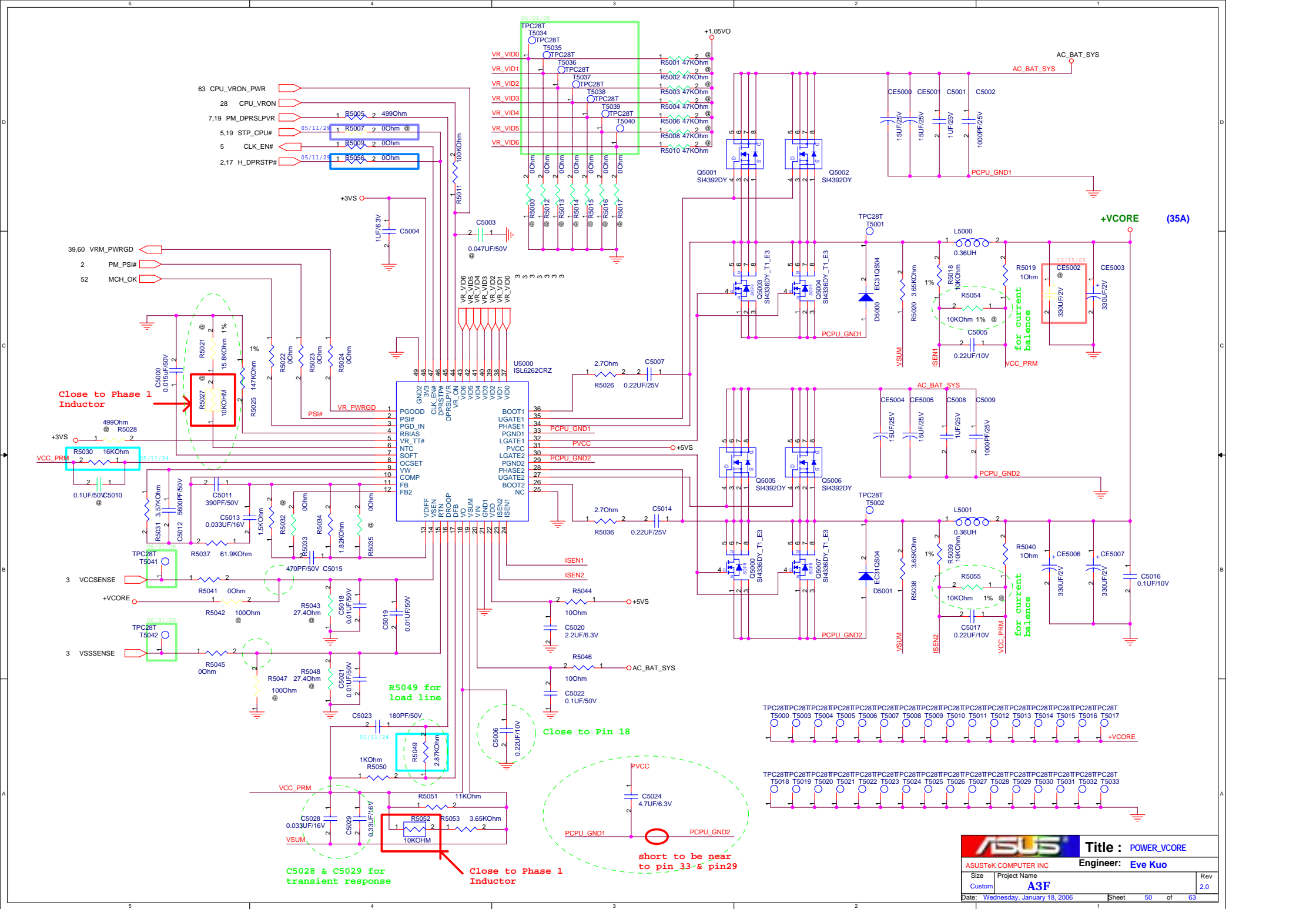
Document Number
A3F

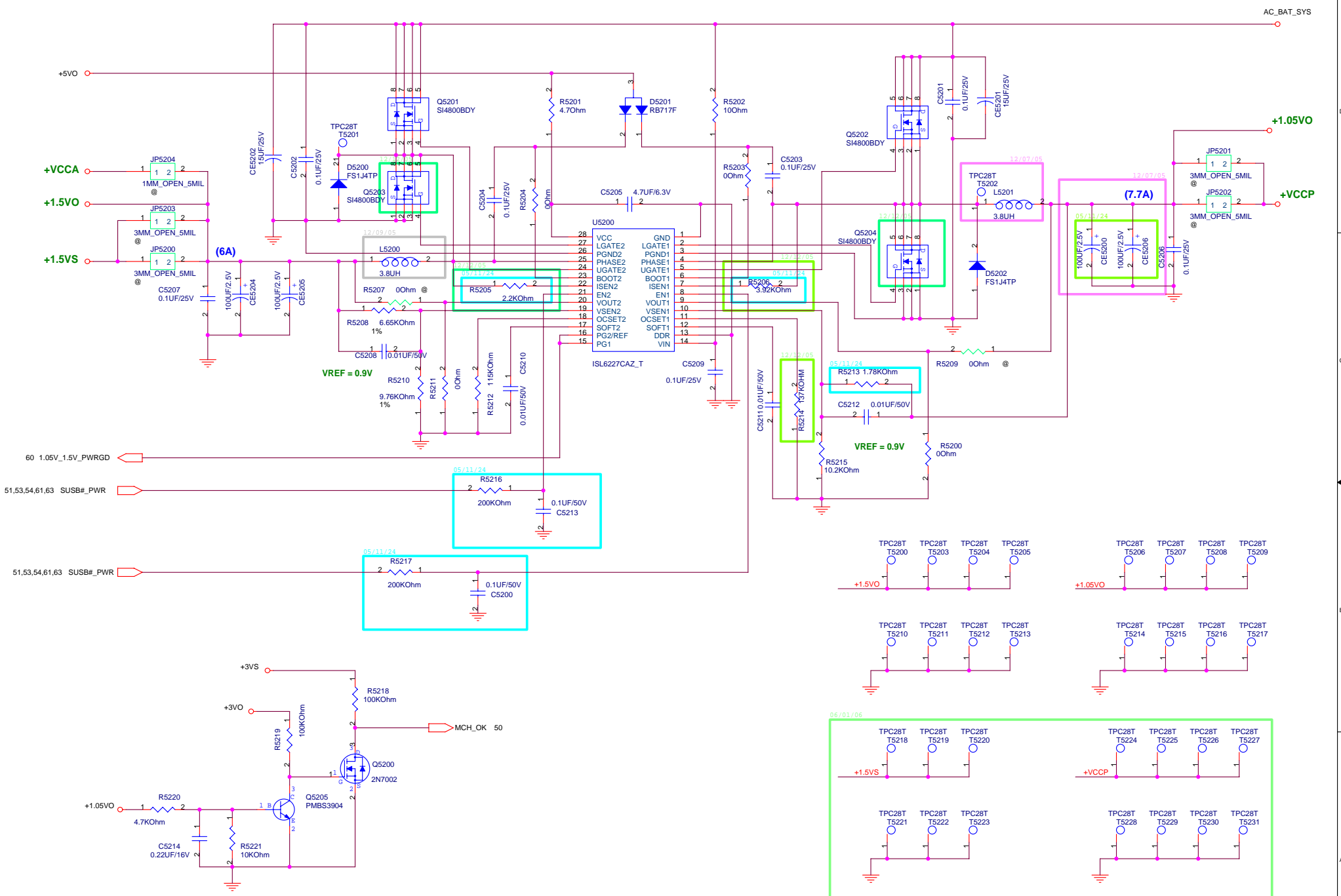
Rev	2.0
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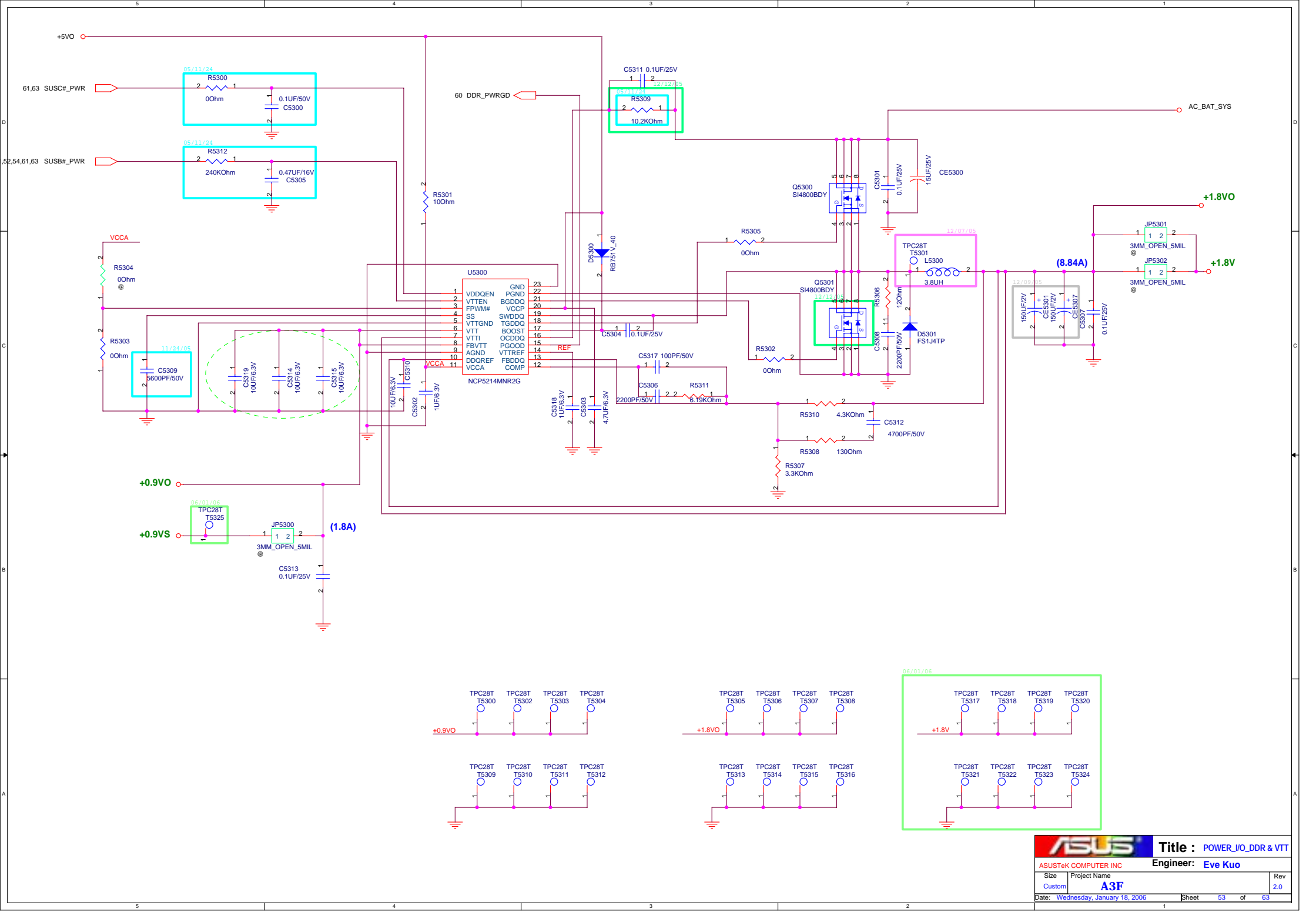
Date: Wednesday, January 18, 2006 Sheet 45 of 63



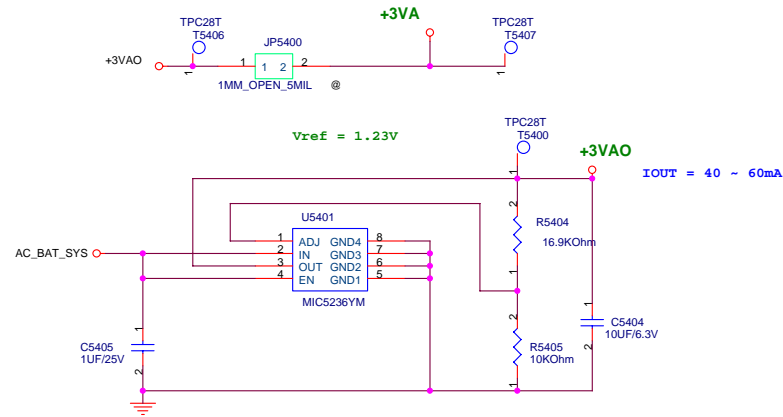




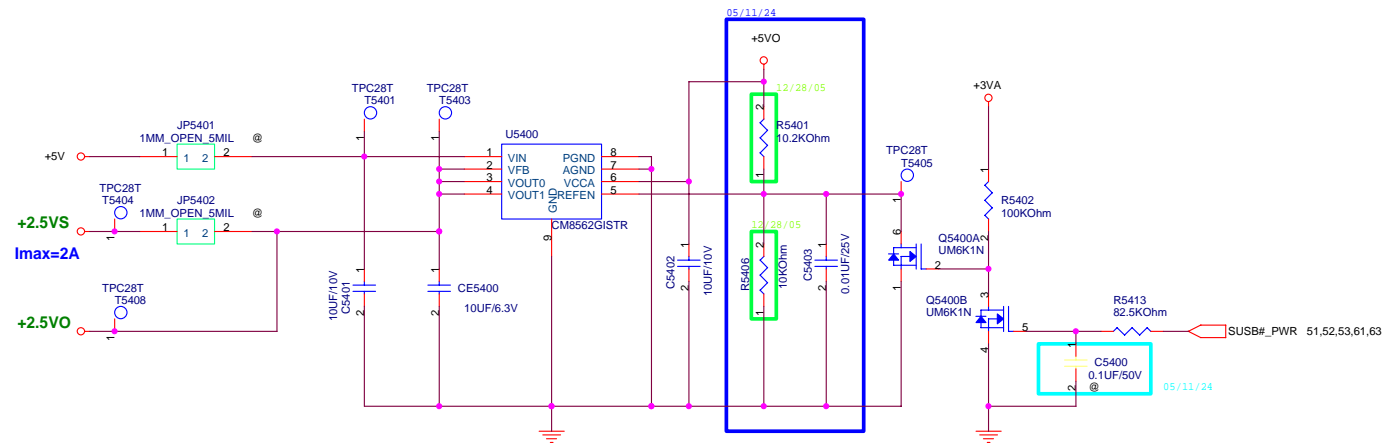




+3VAO



+2.5VS



R1.0

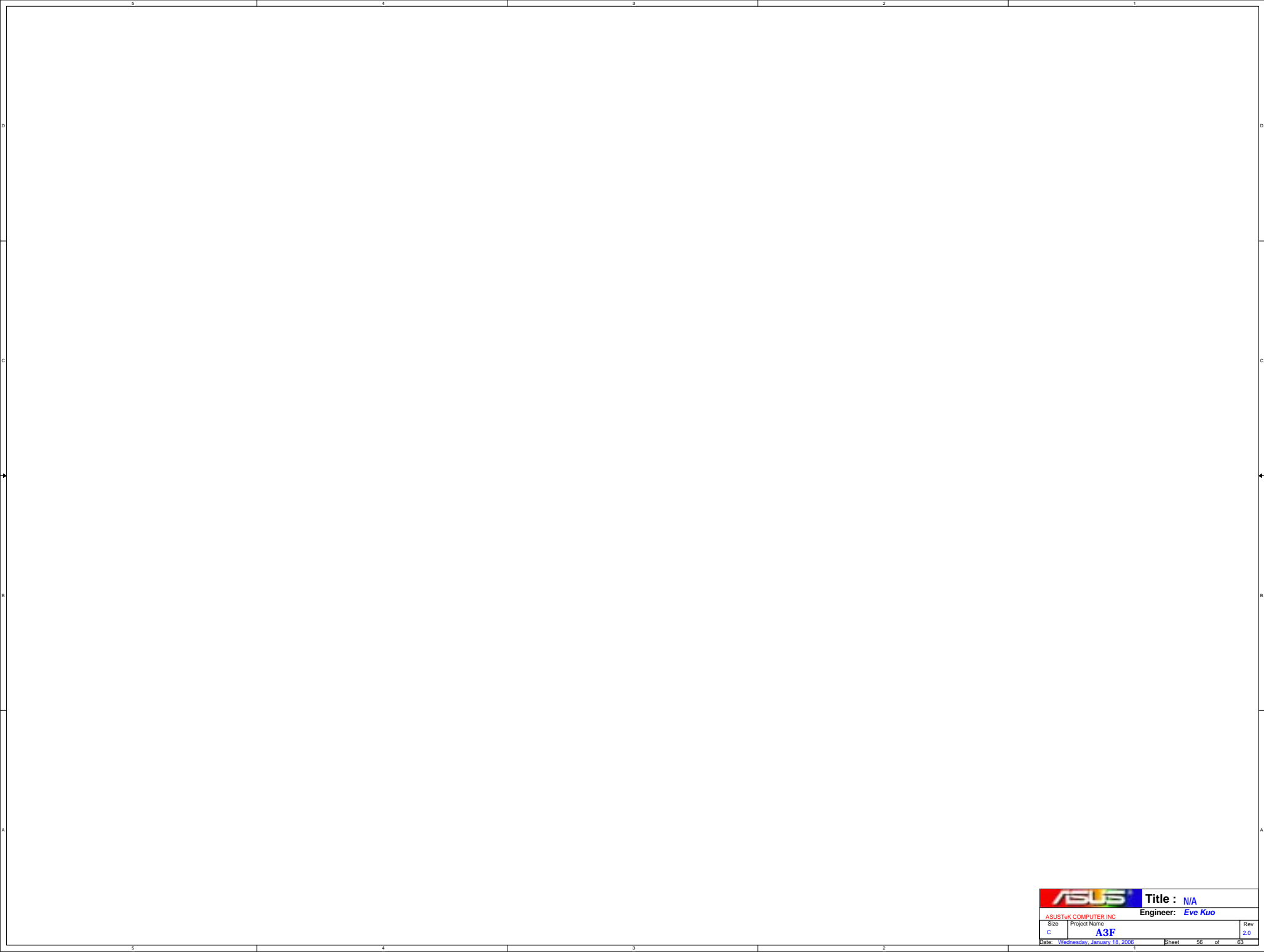
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R1.1

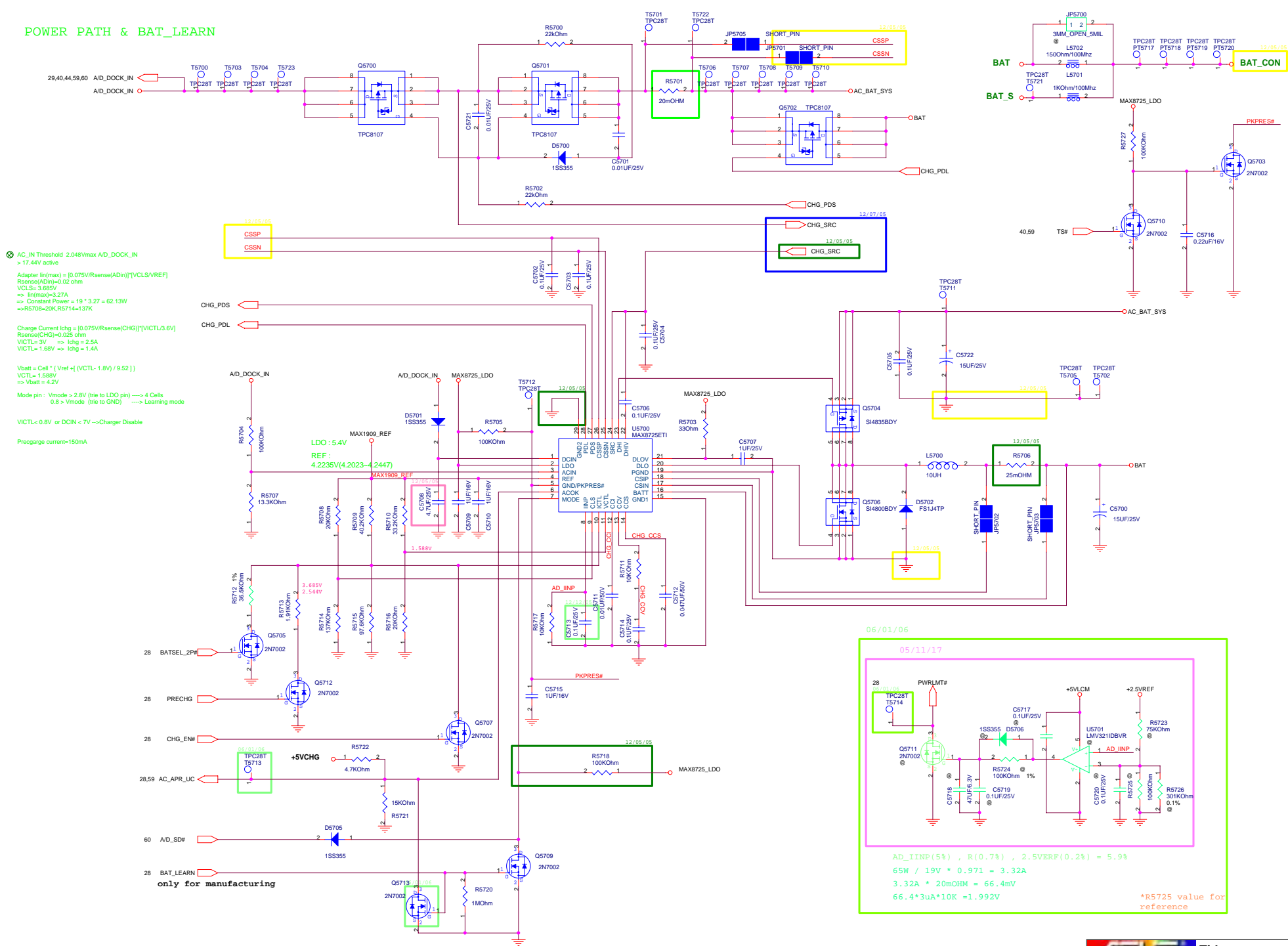
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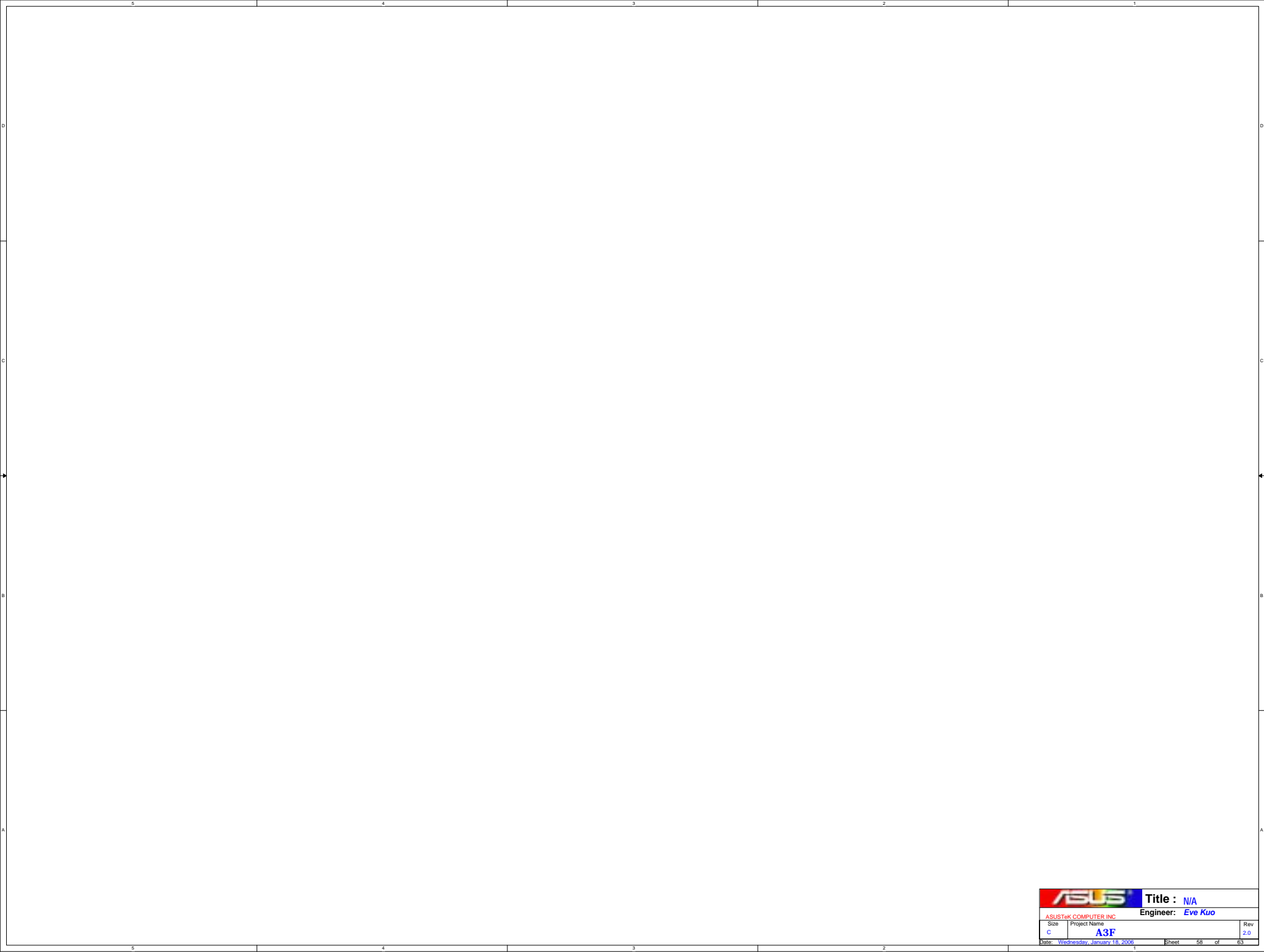
R2.0

Item	Before	After	Reason	Owner	Date

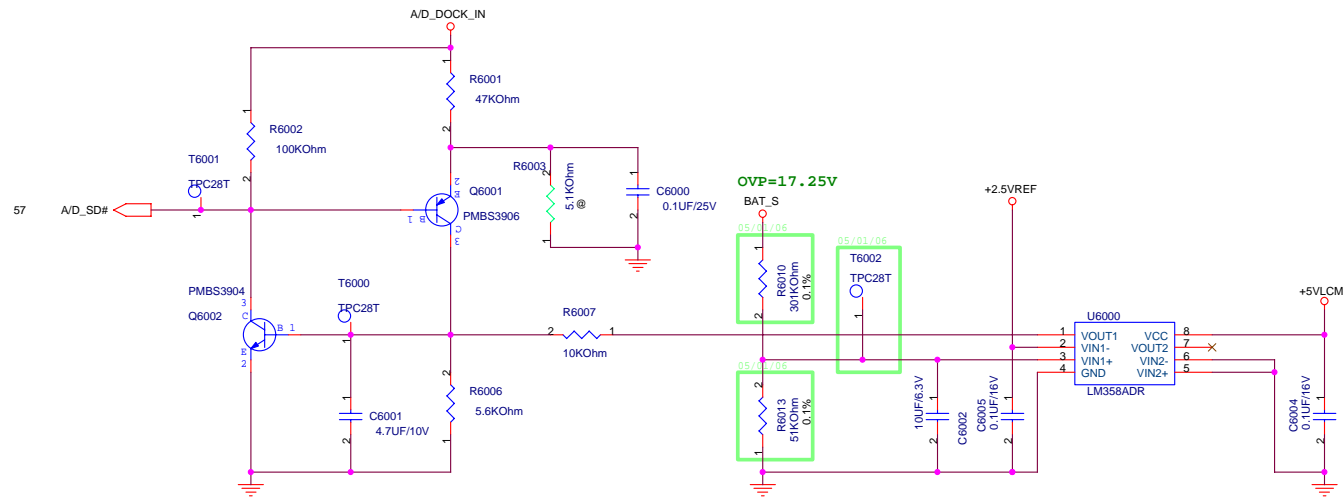


POWER PATH & BAT_LEARN

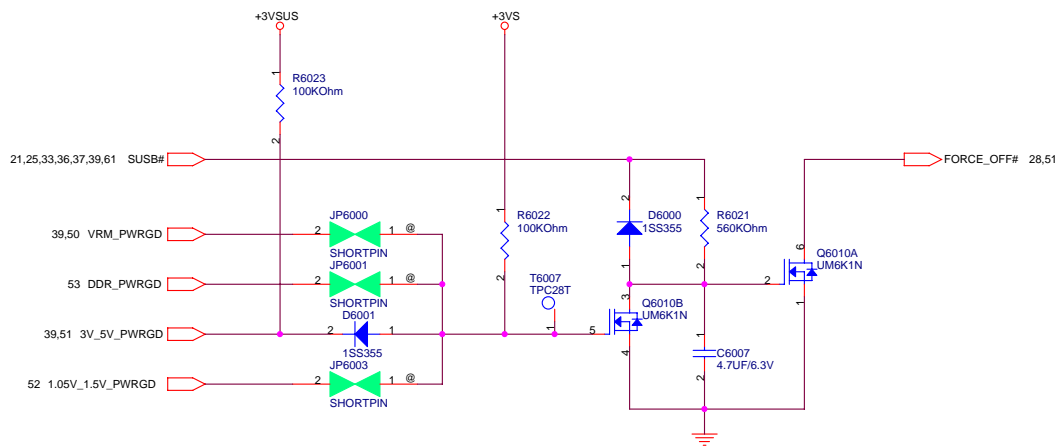




BATTERY A/D_SD# (OVP)

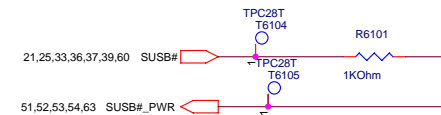


POWER GOOD DETECTER

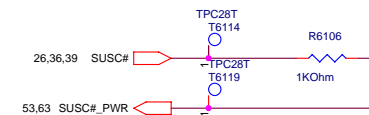


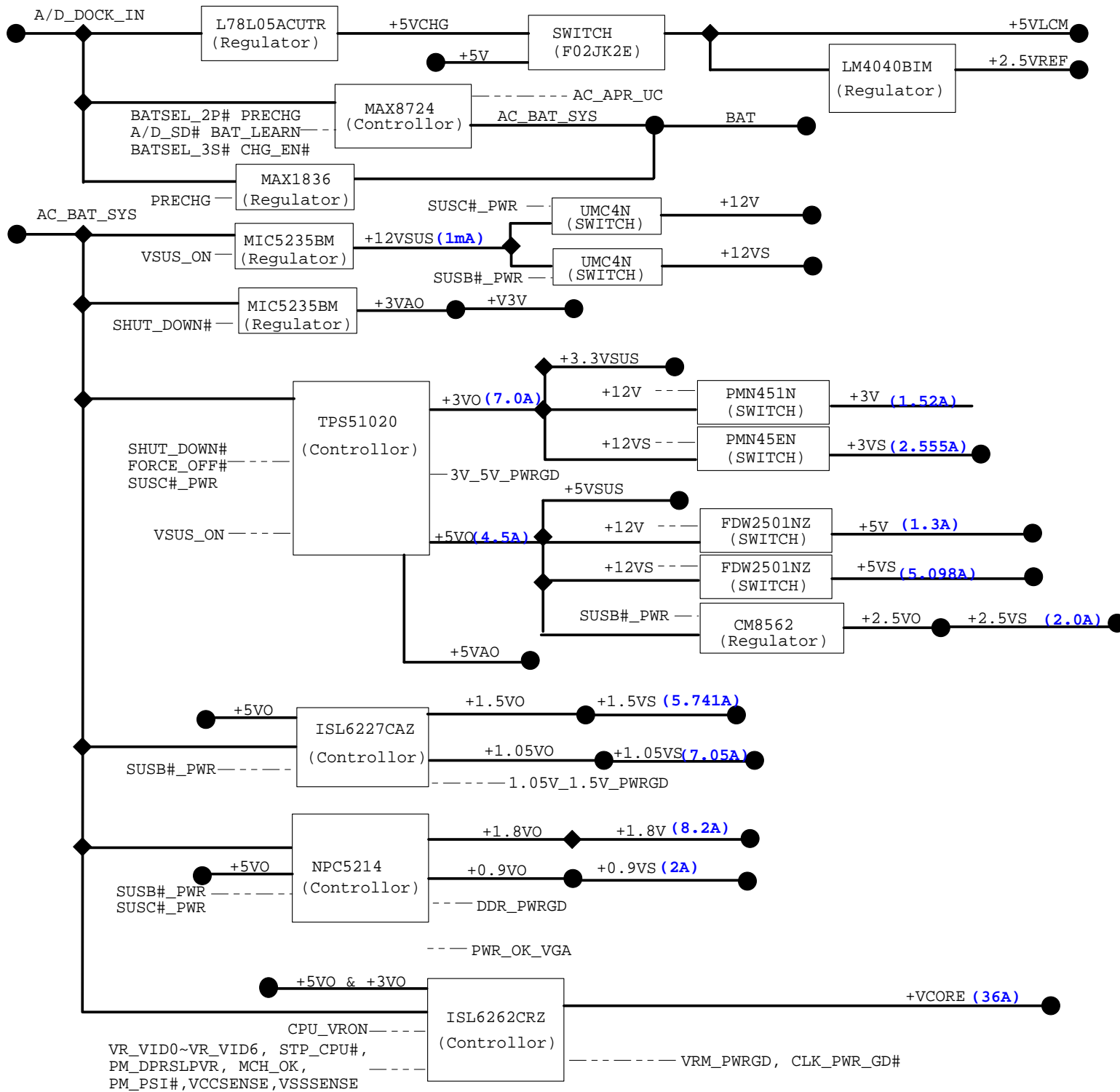
TPC28T	T6003	VRM_PWRGD
TPC28T	T6004	DDR_PWRGD
TPC28T	T6005	3V_5V_PWRGD
TPC28T	T6006	1.05V_1.5V_PWRGD

SUSC#_PWR POWER



SUSB#_PWR POWER







FOR POWER TEST

